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April 1st, 2010
Renesas Electronics Corporation

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7547 Group List of Registers

1. Abstract

This documents describes the 7547 Group registers.

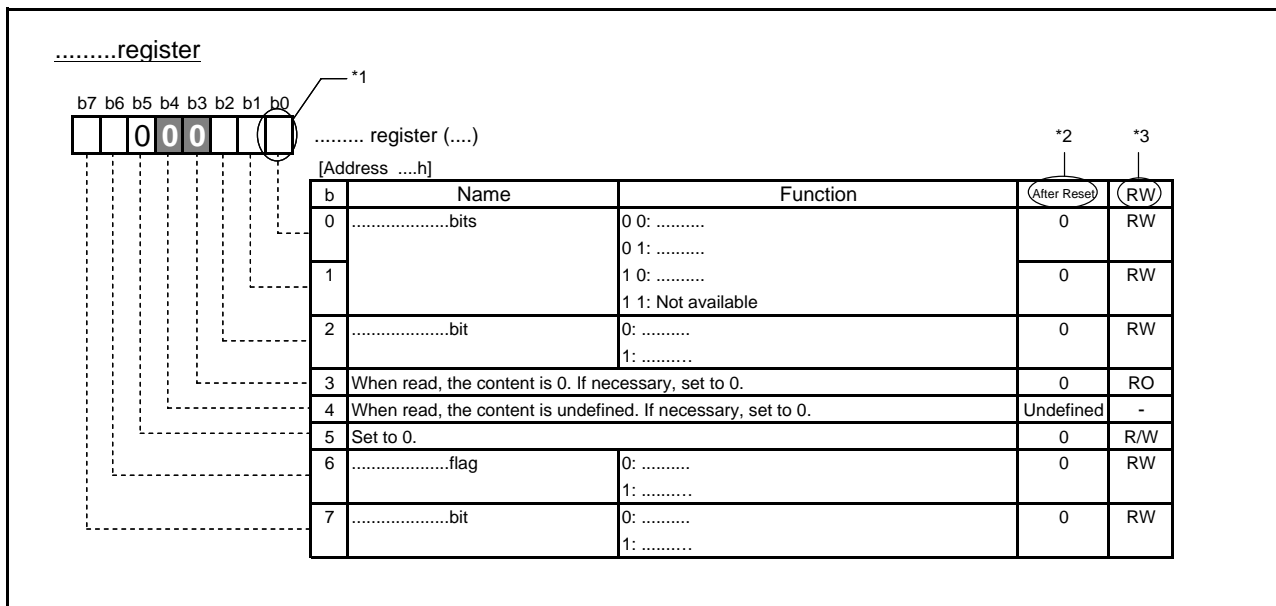
2. Introduction

The registers described in this document are applied to the following:

MCU: 7547 Group

3. Register Configuration

The following shows an example of a control register configuration diagram in this application note, and the definitions of the symbols and terms used in the diagram.



*1
 Blank : Set to 0 or 1 according to the application.
 0 : Set to 0.
 1 : Set to 1.
 x : This bit is not used in the specific mode or state. Set to either 0 or 1.
 [Grey Box] : Nothing is assigned.

*2
 0 : 0 after reset
 1 : 1 after reset
 Undefined : Undefined after reset

*3
 RW : Read and Write.
 RO : Read only. When written, the content depends on each bit.
 WO : Write only. When read, the content is undefined.
 - : When read, the content is undefined. When written, the content depends on each bit.

4. List of Registers

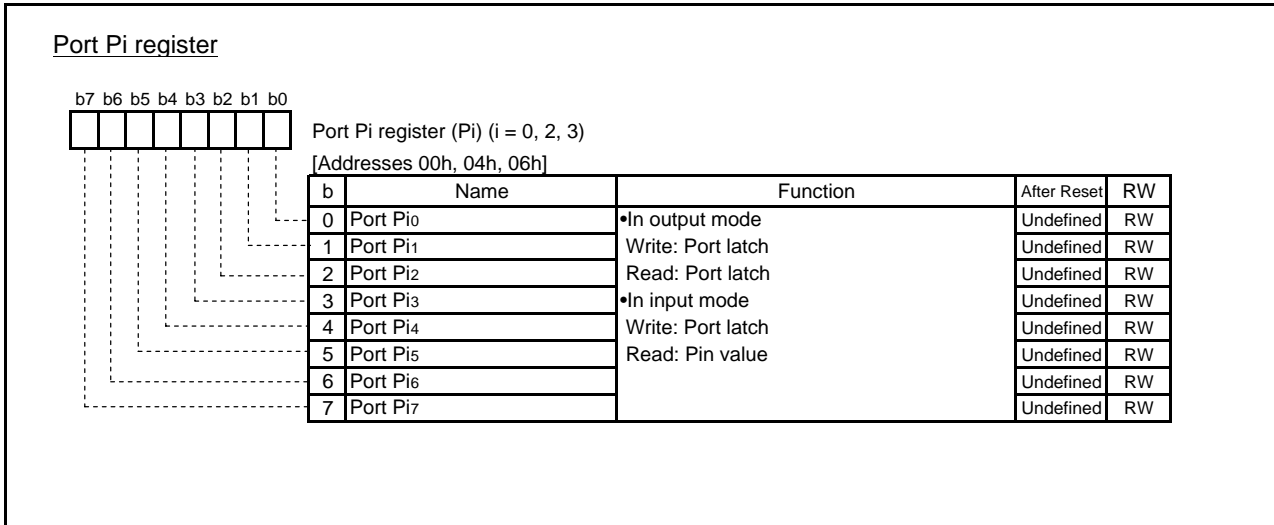


Fig. 4.1 Configuration of Port Pi register (i = 0, 2, 3)

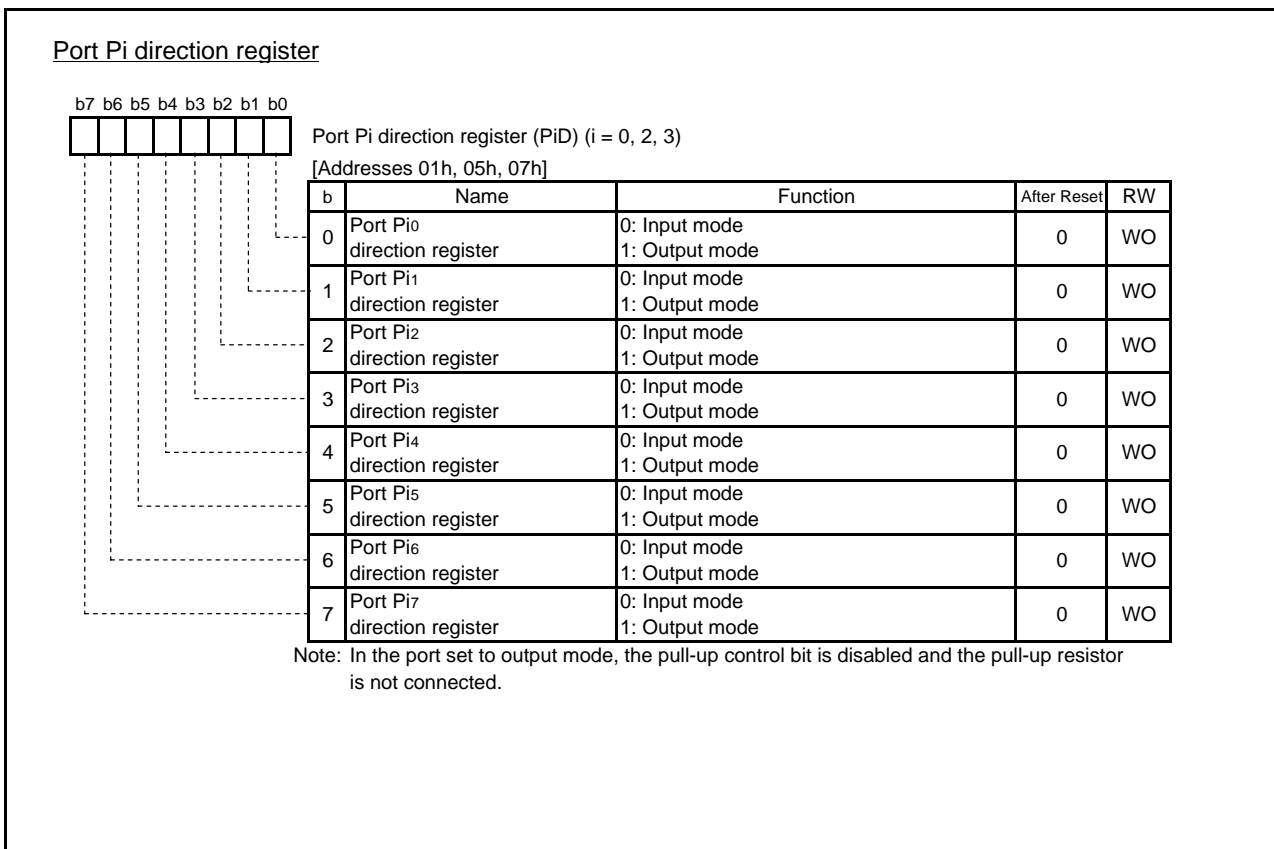


Fig. 4.2 Configuration of Port Pi direction register (i = 0, 2, 3)

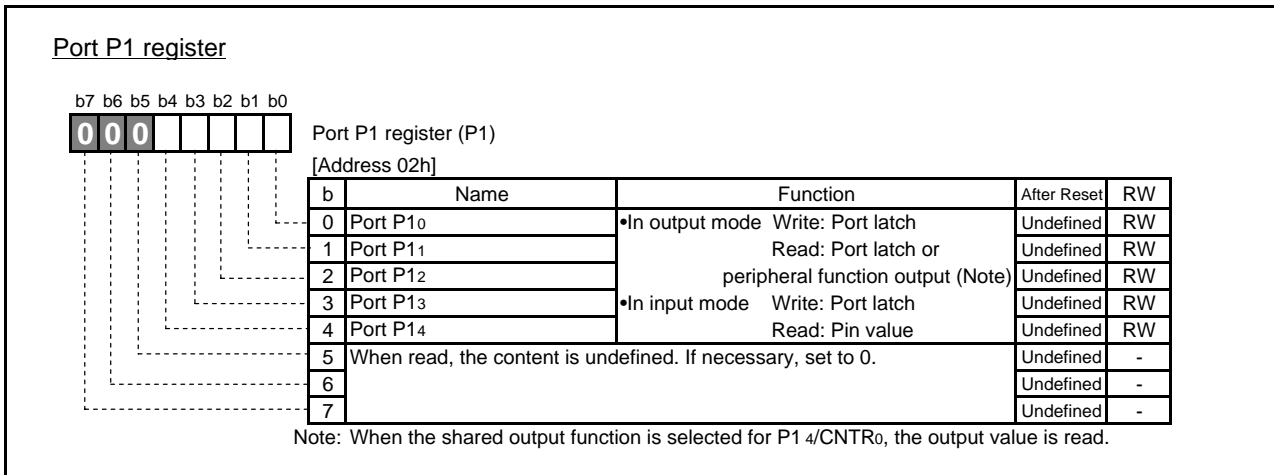


Fig. 4.3 Configuration of Port P1 register

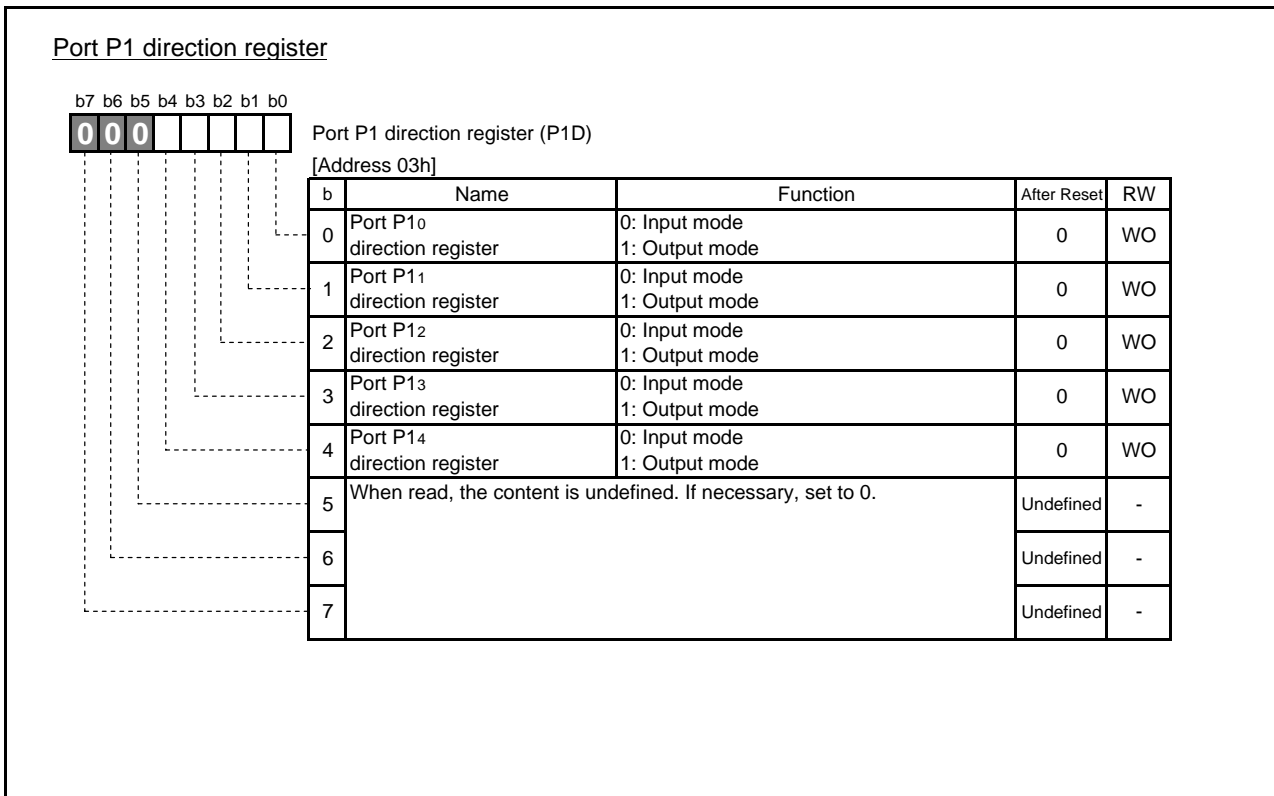


Fig. 4.4 Configuration of Port P1 direction register

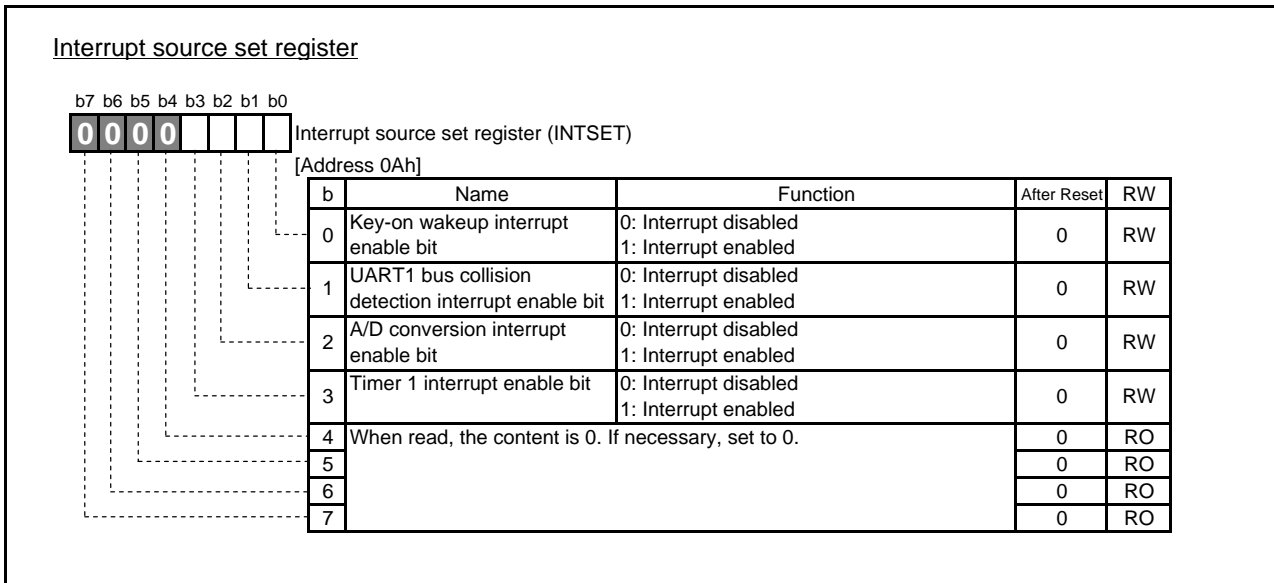


Fig. 4.5 Configuration of Interrupt source set register

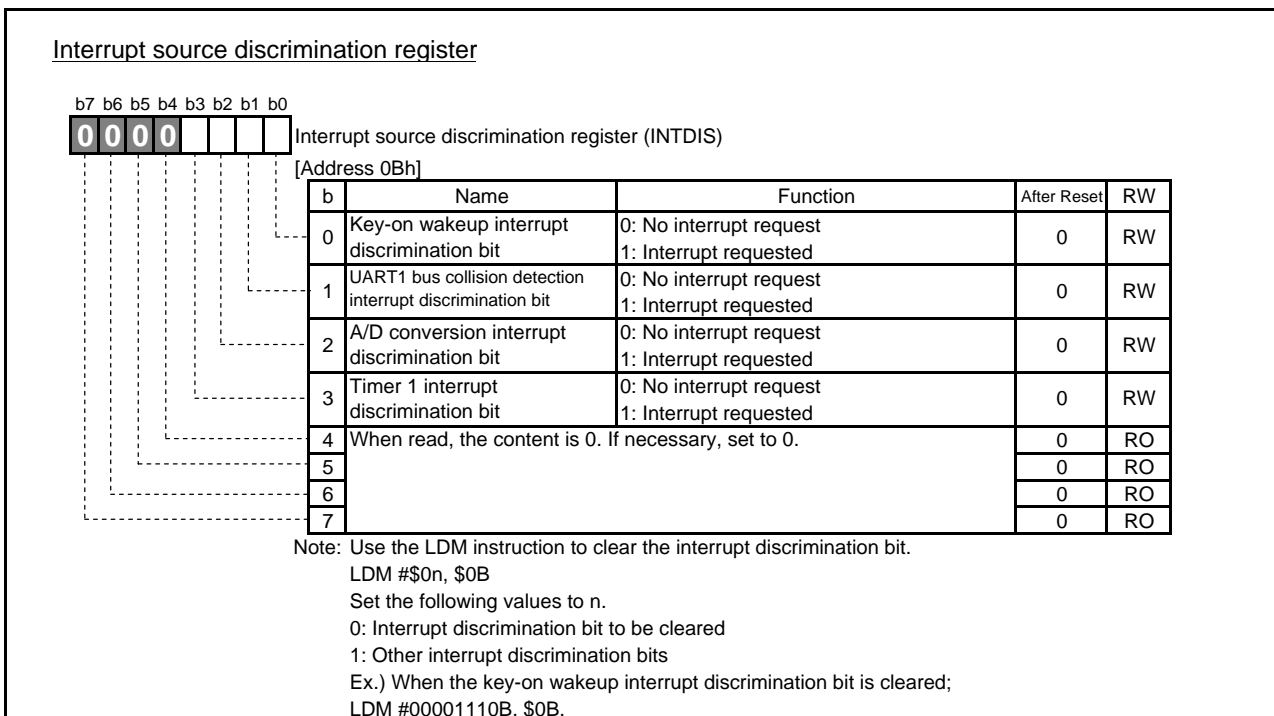


Fig. 4.6 Configuration of Interrupt source discrimination register

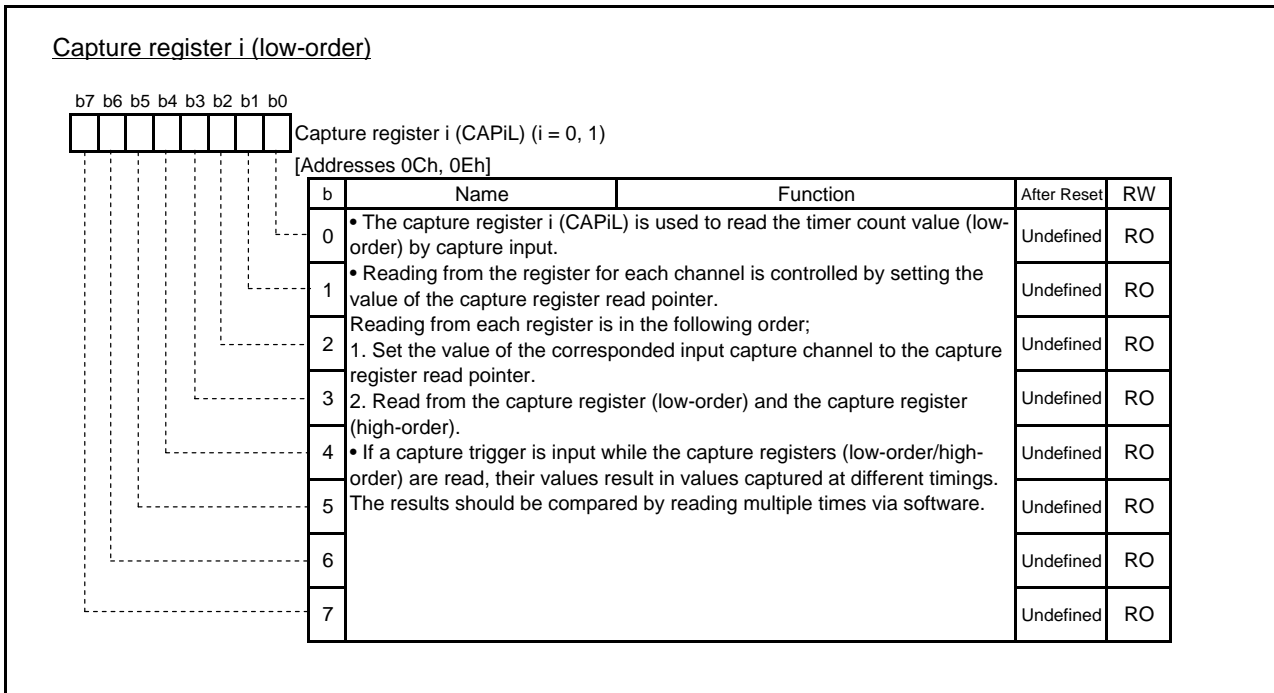


Fig.4.7 Configuration of Capture register i (low-order)

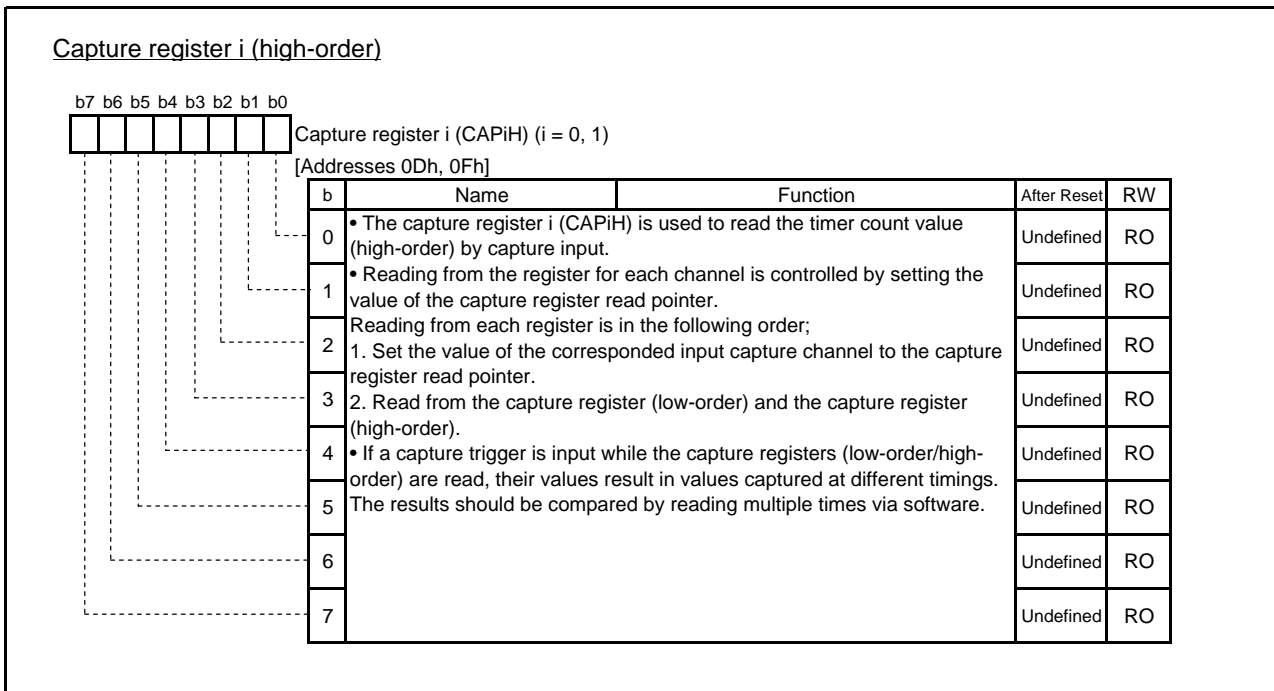
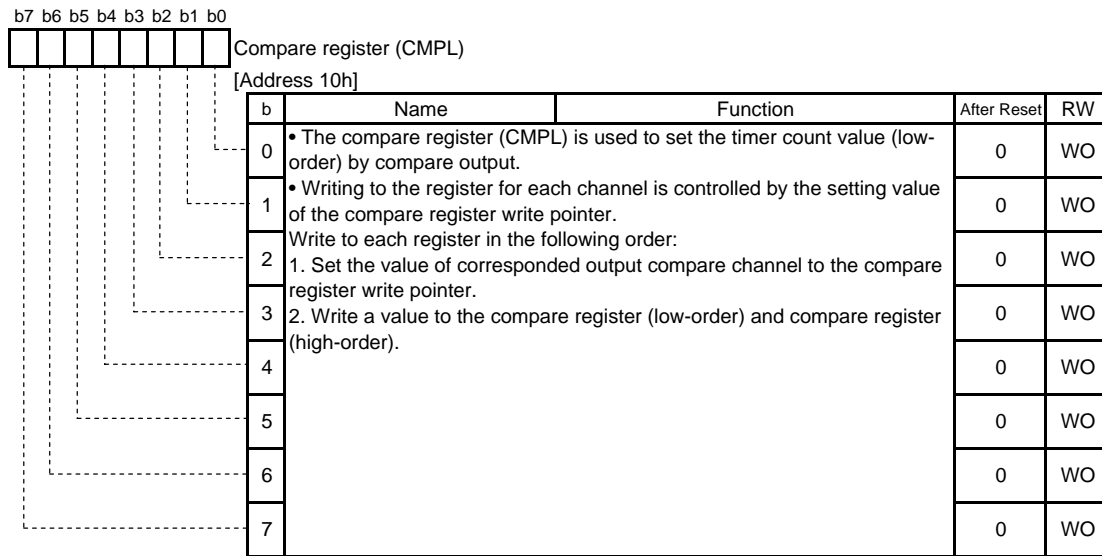


Fig.4.8 Configuration of Capture register i (high-order)

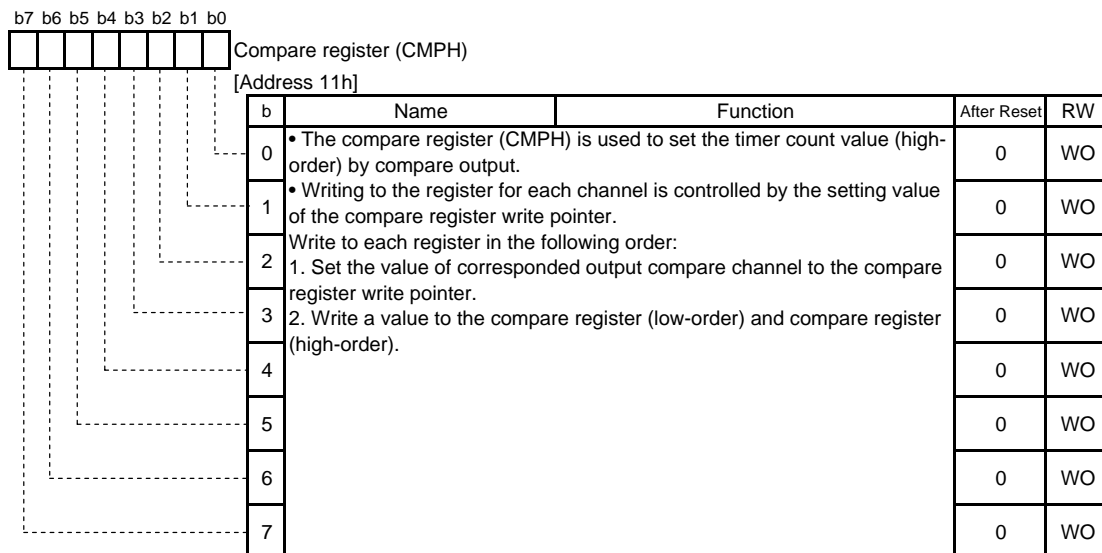
Compare register (low-order)



- Notes 1: When the selected source timer of each compare channel is stopped, written data to compare register is loaded to the compare latch simultaneously.
- 2: Do not write the same value to compare latch x0 and x1 (x = 0, 1, 2, 3).
- 3: When the setting value of the compare latch is larger than the timer setting value, no compare match signal is generated. This allows the output waveform to be fixed to "L" or "H" level. However, when the setting value of another compare latch is smaller than the timer setting value, the compare match signal is generated so that the compare match interrupt occurs.

Fig.4.9 Configuration of Compare register (low-order)

Compare register (high-order)



- Notes 1: When the selected source timer of each compare channel is stopped, written data to compare register is loaded to the compare latch simultaneously.
- 2: Do not write the same value to both compare latch x0 and x1 (x = 0, 1, 2, 3).
- 3: When the setting value of the compare latch is larger than the timer setting value, no compare match signal is generated. This allows the output waveform to be fixed to "L" or "H" level. However, when the setting value of another compare latch is smaller than the timer setting value, the compare match signal is generated so that the compare match interrupt occurs.

Fig.4.10 Configuration of Compare register (high-order)

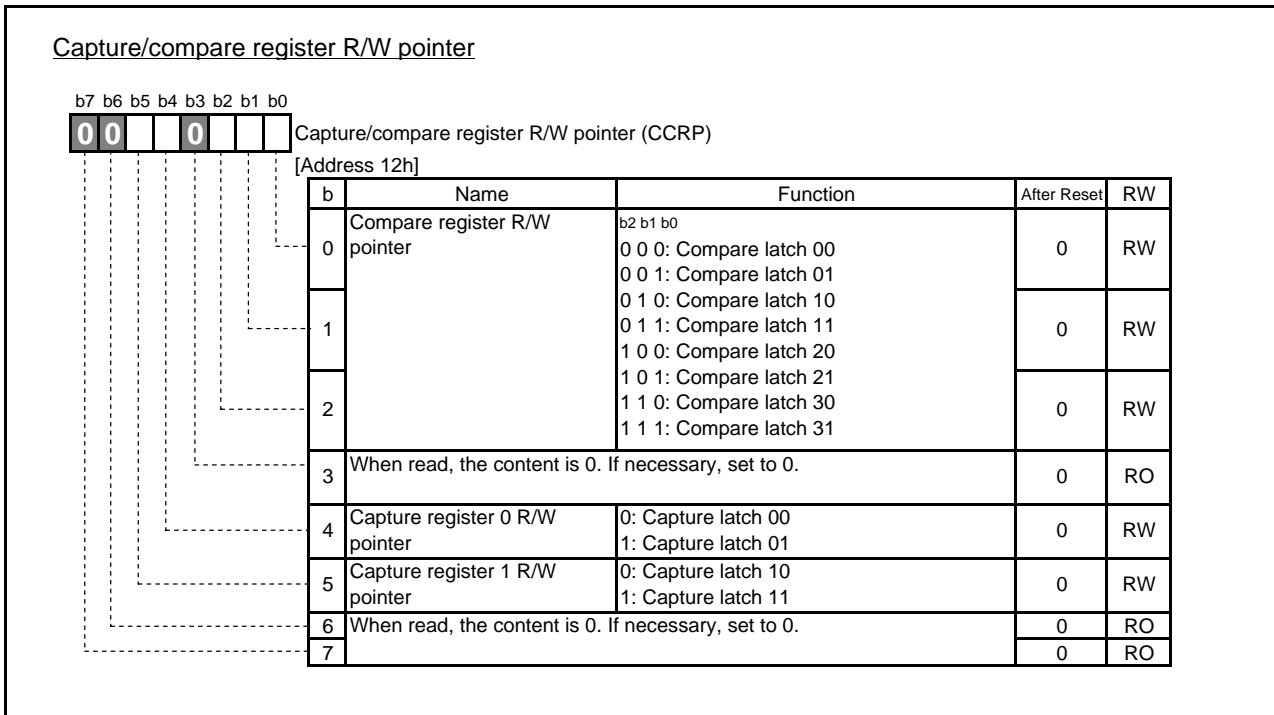


Fig. 4.11 Configuration of Capture/compare register R/W pointer

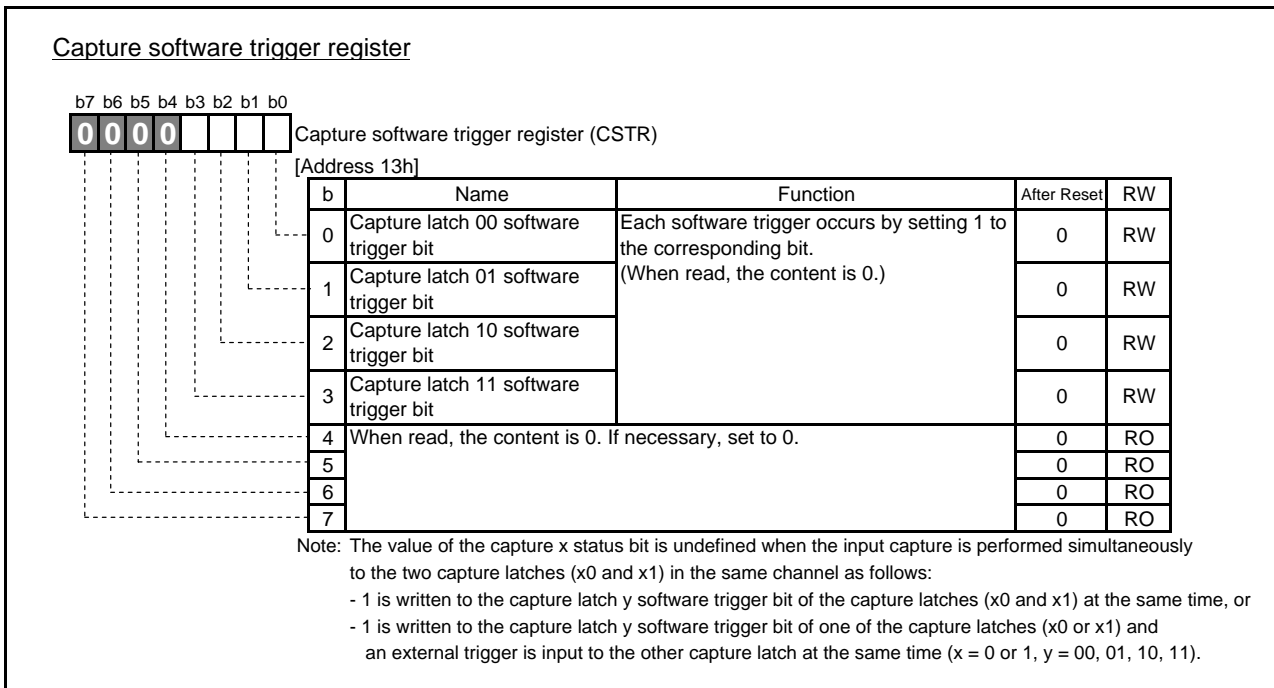
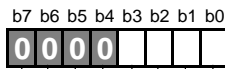


Fig. 4.12 Configuration of Capture software trigger register

Compare register re-load register



Compare register re-load register (CMPR)

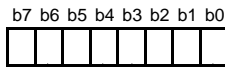
[Address 14h]

b	Name	Function	After Reset	RW
0	Compare latch 00, 01 re-load bit	0: Re-load disabled 1: Re-load at next underflow	0	RW
1	Compare latch 10, 11 re-load bit	0: Re-load disabled 1: Re-load at next underflow	0	RW
2	Compare latch 20, 21 re-load bit	0: Re-load disabled 1: Re-load at next underflow	0	RW
3	Compare latch 30, 31 re-load bit	0: Re-load disabled 1: Re-load at next underflow	0	RW
4	When read, the content is 0. If necessary, set to 0.		0	RO
5			0	RO
6			0	RO
7			0	RO

Note: When 1 is set to the compare latch y re-load bit, the value set in the compare register is loaded to the compare latch corresponding to each channel at the next timer underflow (y = 00, 01, 10, 11, 20, 21, 30, 31).

Fig. 4.13 Configuration of Compare register re-load register

Port P0P3 drive capacity control register



Port P0P3 drive capacity control register (DCCR)

[Address 15h]

b	Name	Function	After Reset	RW
0	Port P0 ₀ drive capacity bit	0: Low 1: High	0	RW
1	Port P0 ₁ , P0 ₂ drive capacity bit	0: Low 1: High	0	RW
2	Port P0 ₃ -P0 ₇ drive capacity bit	0: Low 1: High	0	RW
3	Port P3 ₀ drive capacity bit	0: Low 1: High	0	RW
4	Port P3 ₁ , P3 ₂ drive capacity bit	0: Low 1: High	0	RW
5	Port P3 ₃ drive capacity bit	0: Low 1: High	0	RW
6	Port P3 ₄ , P3 ₅ drive capacity bit	0: Low 1: High	0	RW
7	Port P3 ₆ , P3 ₇ drive capacity bit	0: Low 1: High	0	RW

Note: The maximum number of available ports (drive capacity: High) is eight.

Fig. 4.14 Configuration of Port P0P3 drive capacity control register

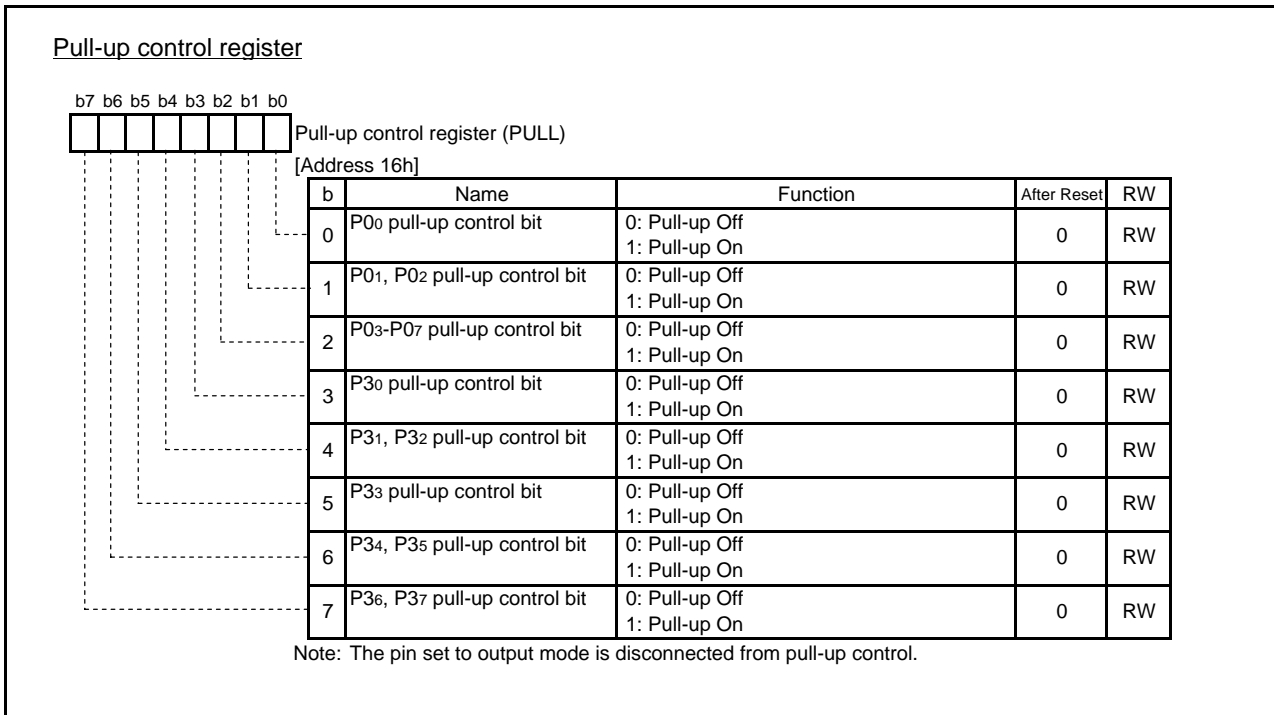


Fig. 4.15 Configuration of Pull-up control register

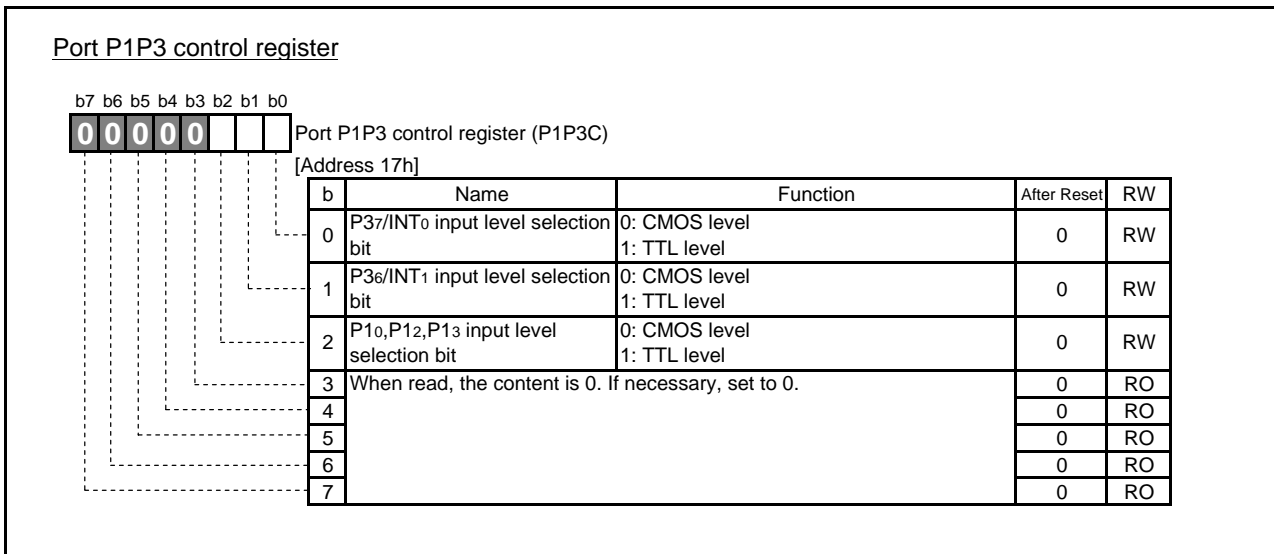
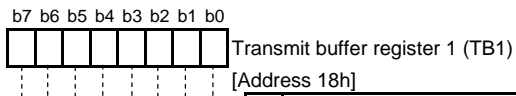


Fig. 4.16 Configuration of Port P1P3 control register

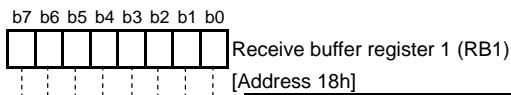
Transmit buffer register 1



b	Function	After Reset	RW
0	The transmission data is written to this buffer register.	Undefined	WO
1	Write transmission data to this register.	Undefined	WO
2		Undefined	WO
3		Undefined	WO
4		Undefined	WO
5		Undefined	WO
6		Undefined	WO
7		Undefined	WO

Note: This register is assigned to the same address as the receive buffer register. Unreadable.

Receive buffer register 1



b	Function	After Reset	RW
0	The receive data is read from this buffer register.	Undefined	RO
1	Read receive data from this register.	Undefined	RO
2		Undefined	RO
3		Undefined	RO
4		Undefined	RO
5		Undefined	RO
6		Undefined	RO
7		Undefined	RO

Note: This register is assigned to the same address as the transmit buffer register. Unwritable.

Fig.4.17 Configuration of Transmit buffer register 1/Receive buffer register 1

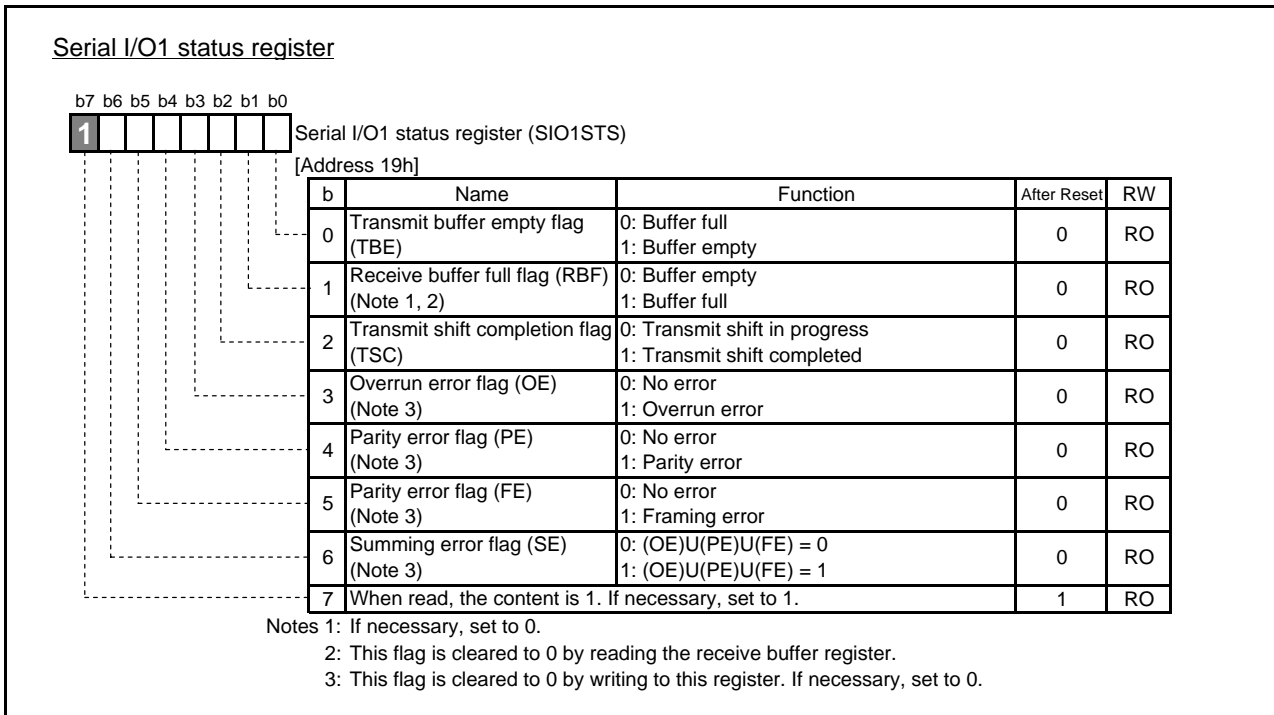


Fig. 4.18 Configuration of Serial I/O1 status register

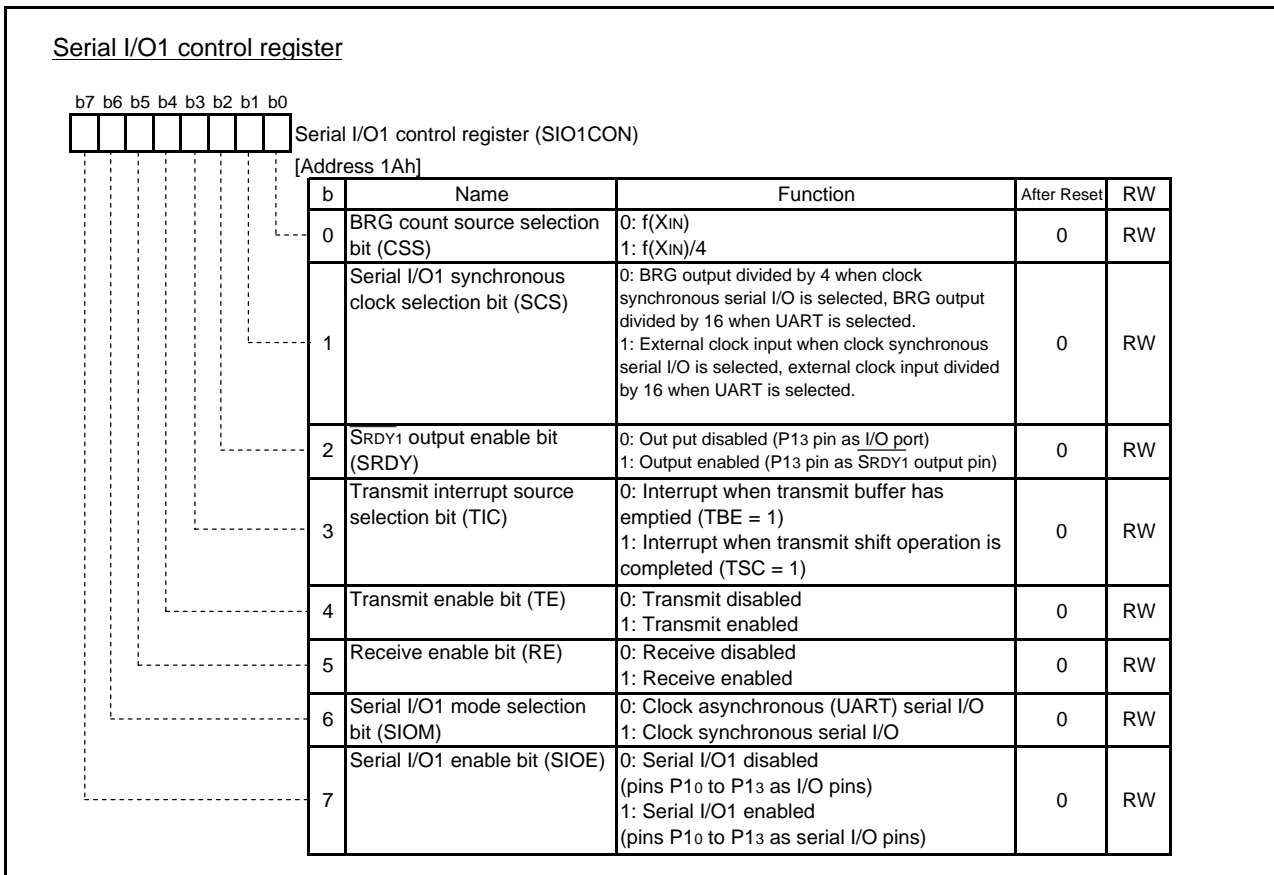


Fig. 4.19 Configuration of Serial I/O1 control register

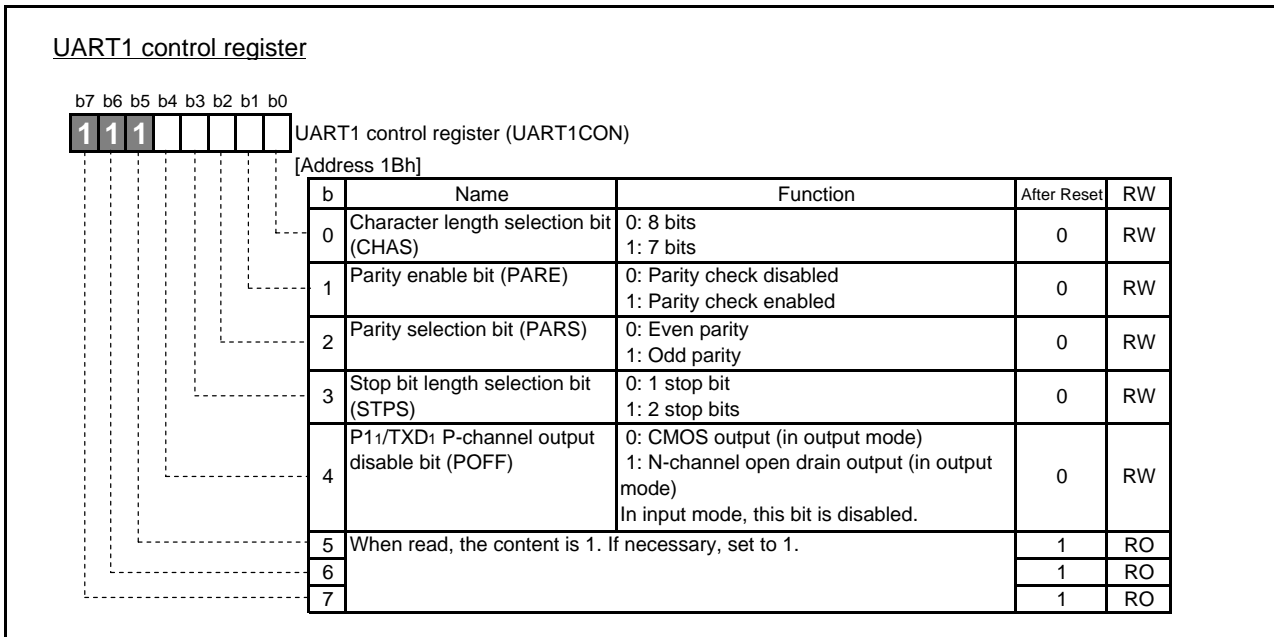


Fig. 4.20 Configuration of UART1 control register

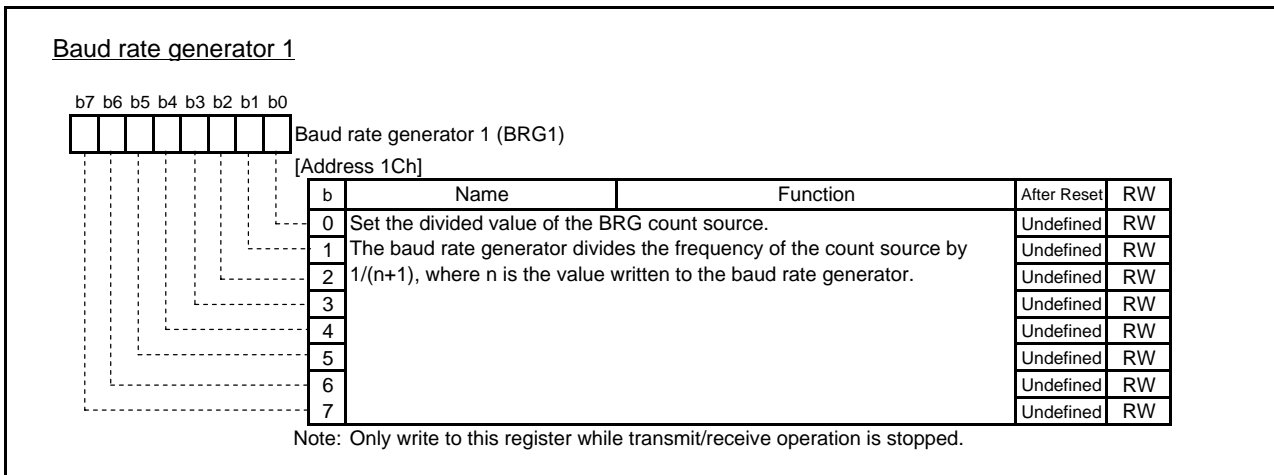


Fig.4.21 Configuration of Baud rate generator 1

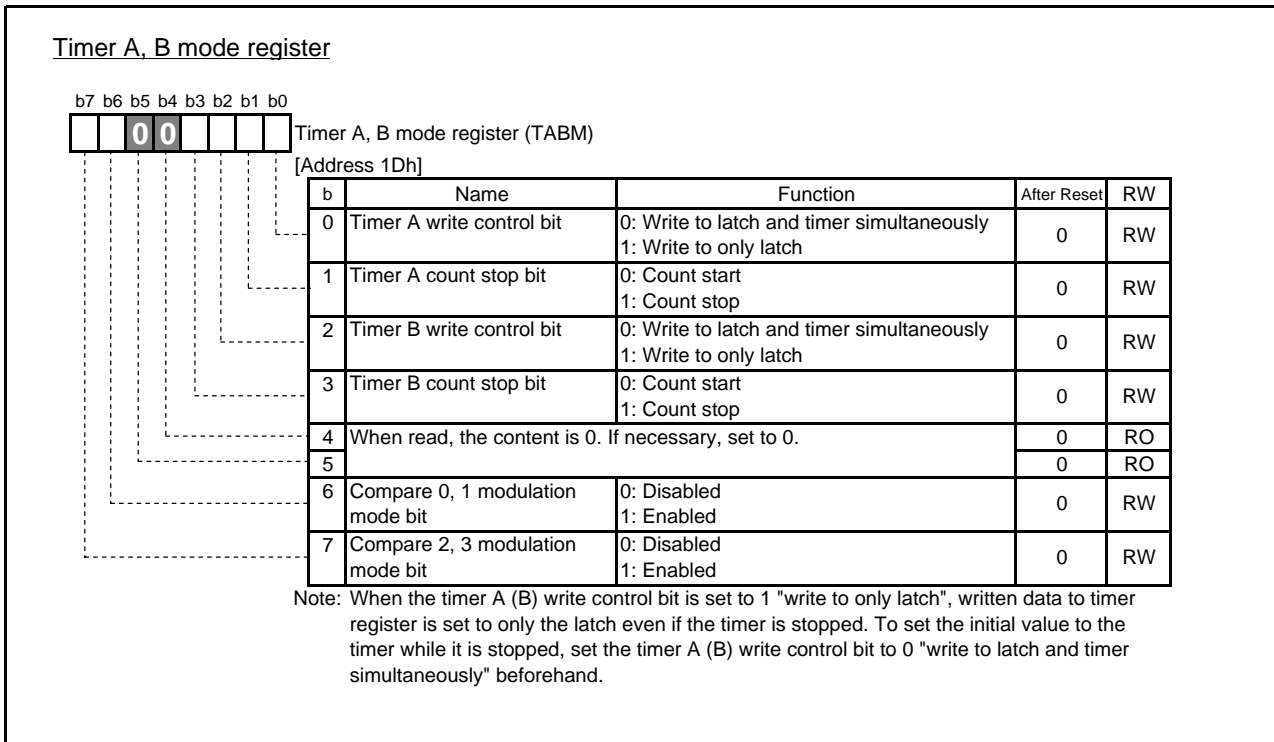


Fig.4.22 Configuration of Timer A, B mode register

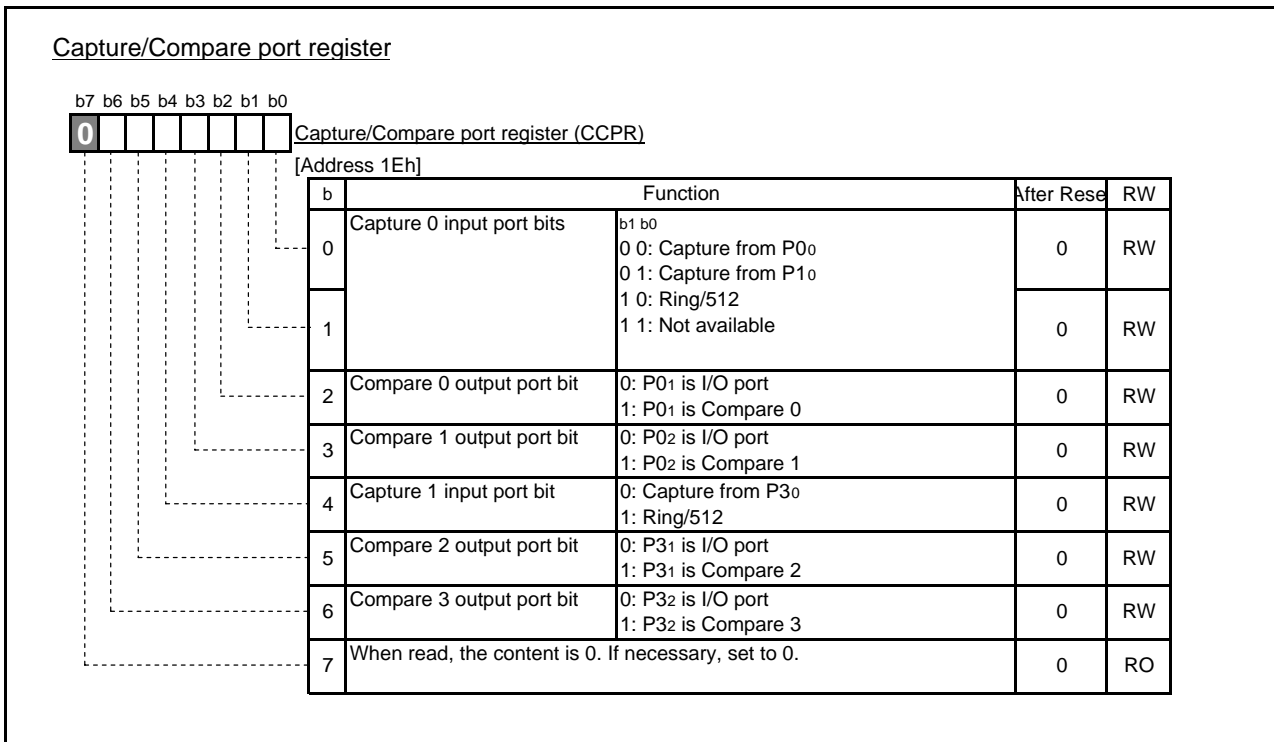


Fig.4.23 Configuration of Capture/Compare port register

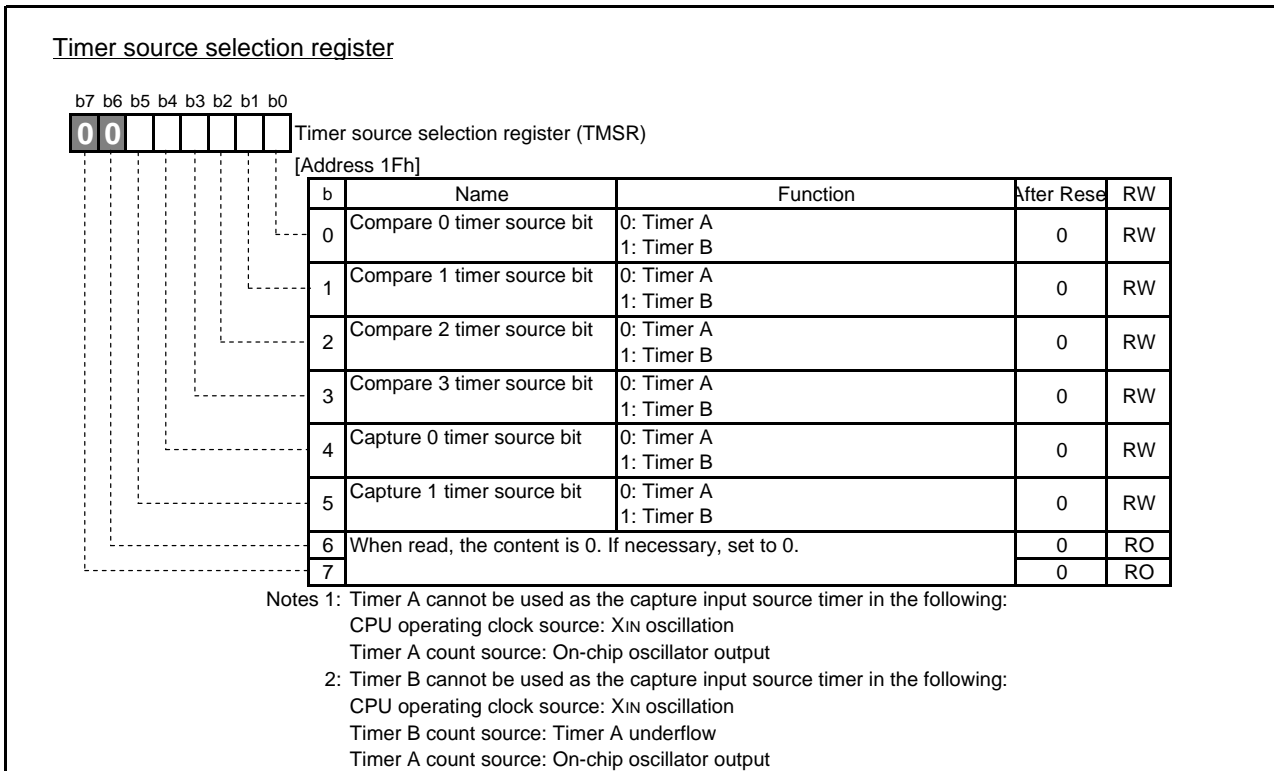


Fig.4.24 Configuration of Timer source selection register

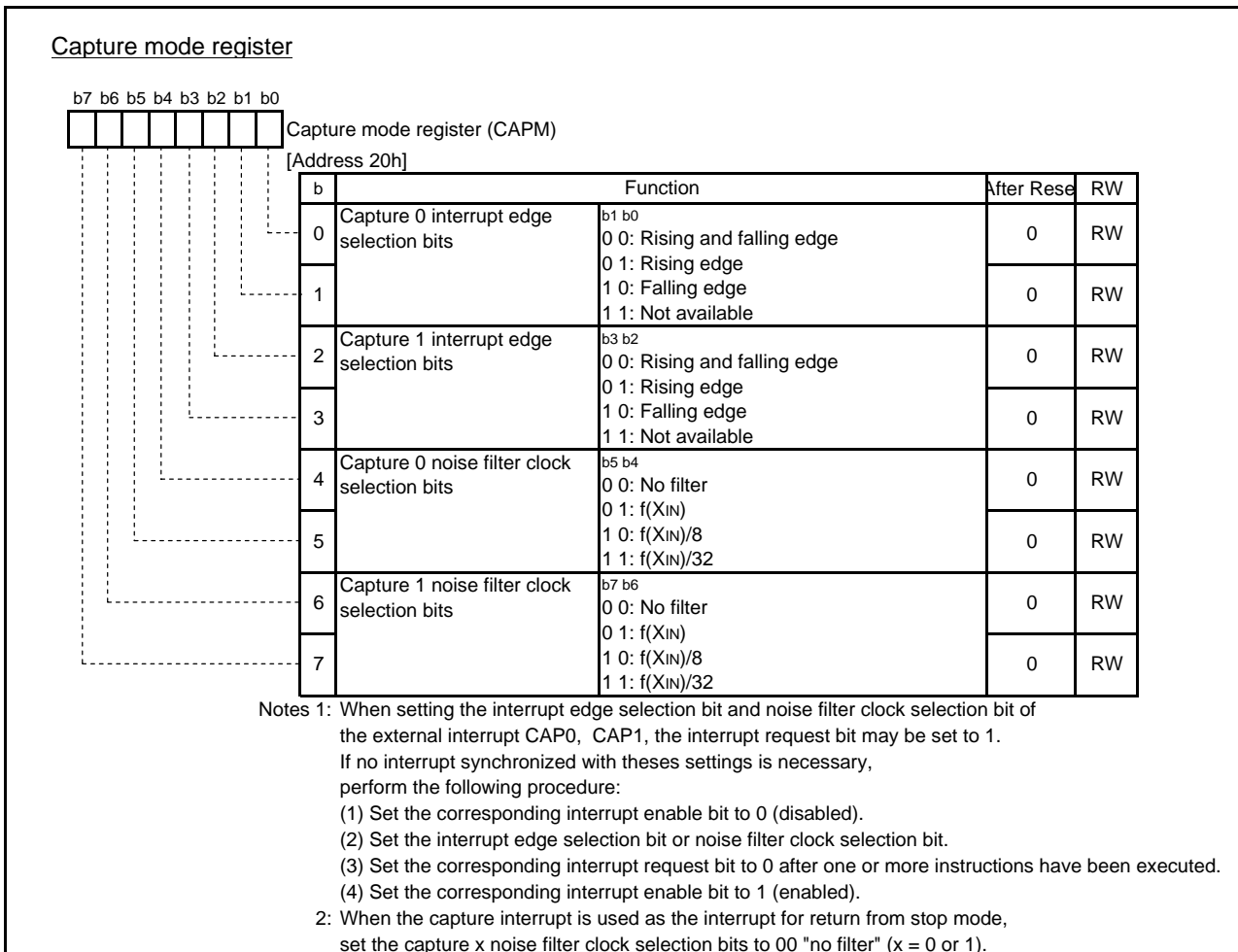


Fig.4.25 Configuration of Capture mode register

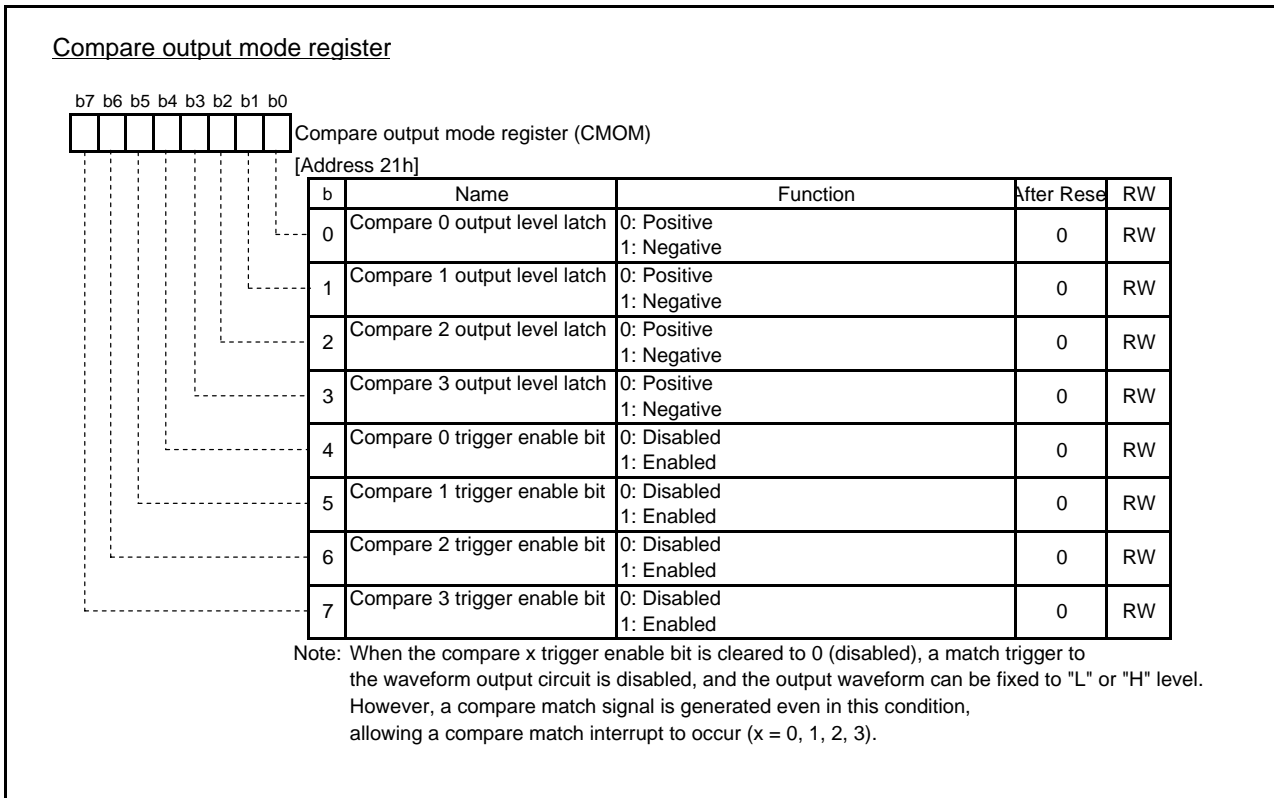


Fig.4.26 Configuration of Compare output mode register

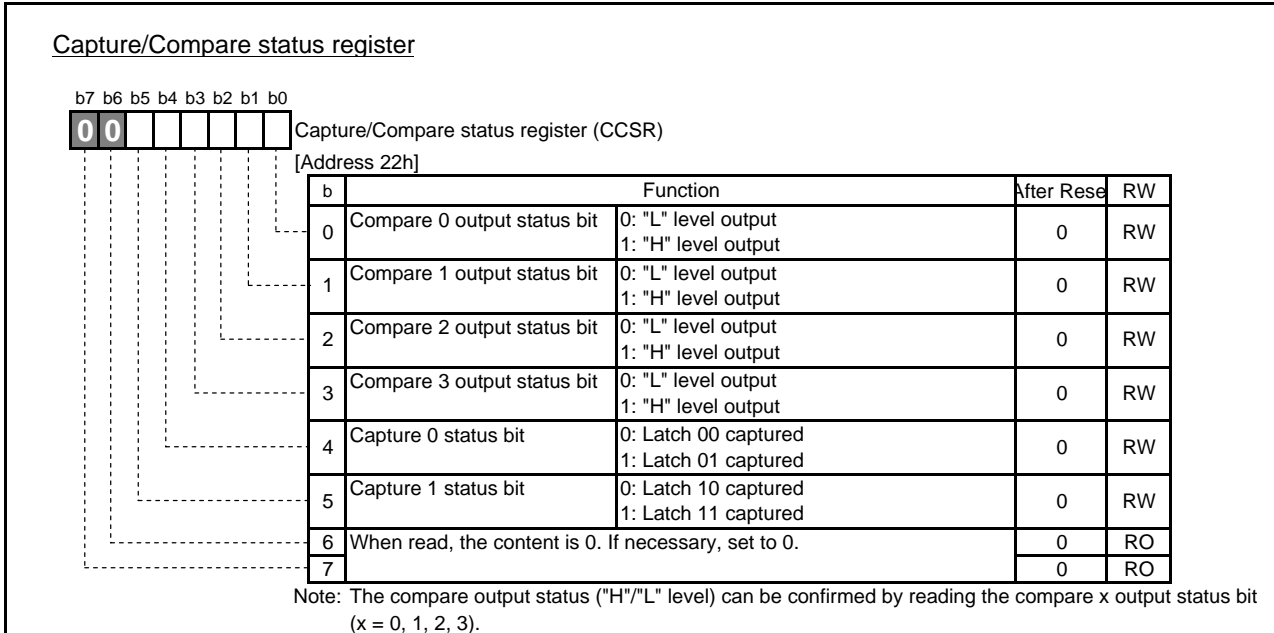


Fig.4.27 Configuration of Capture/Compare status register

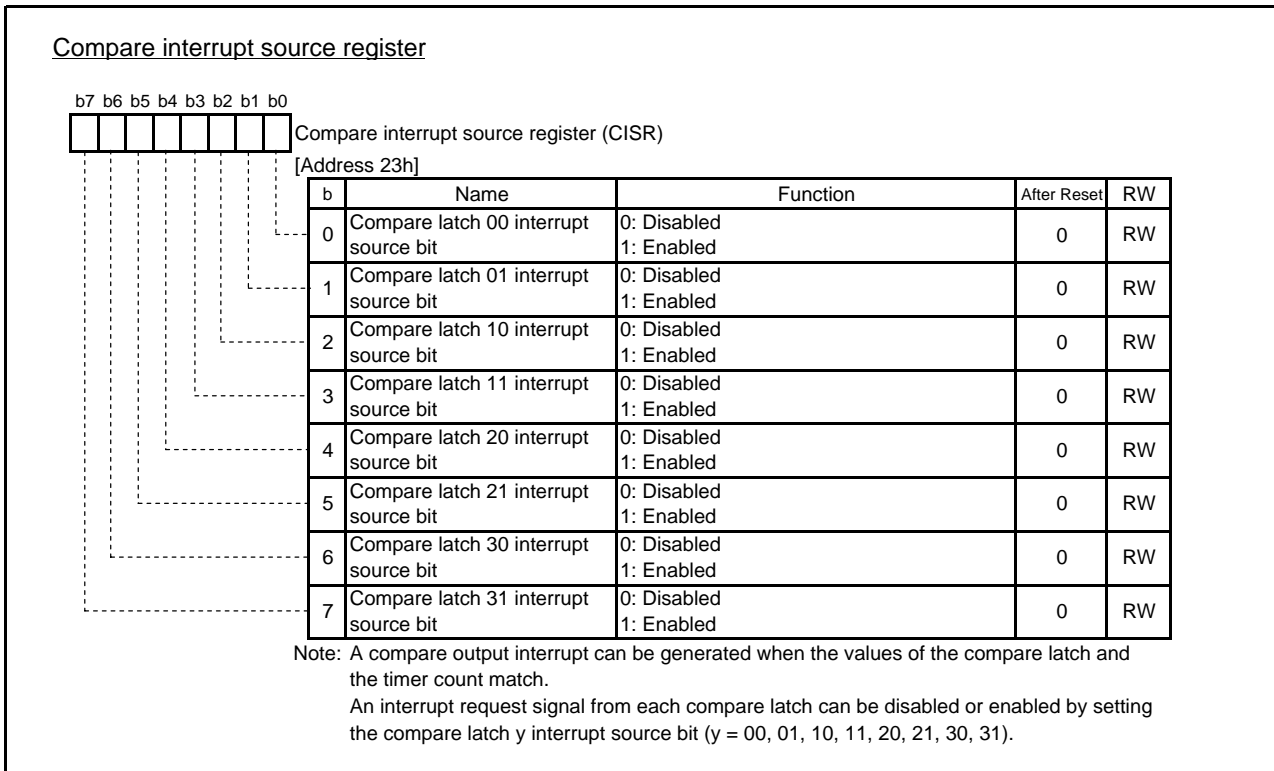


Fig.4.28 Configuration of Compare interrupt source register

Timer A high-order register, Timer A low-order register

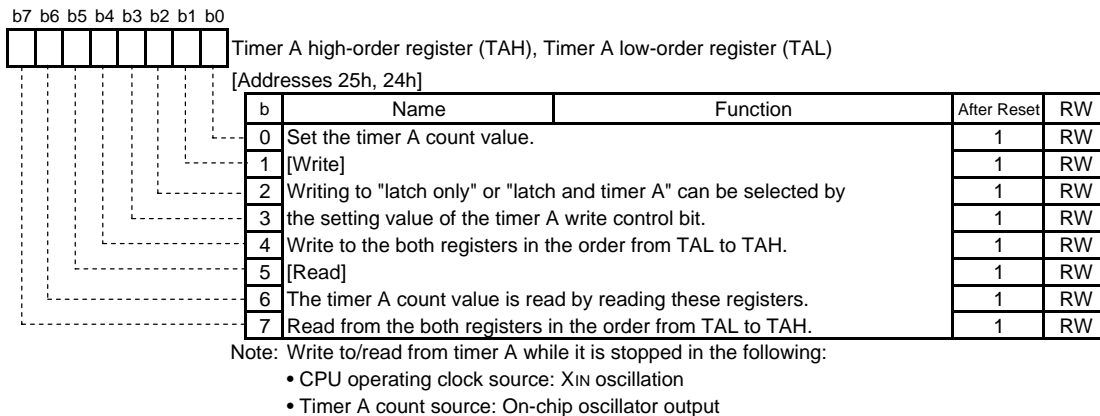


Fig.4.29 Configuration of Timer A high-order register, Timer A low-order register

Timer B high-order register, Timer B low-order register

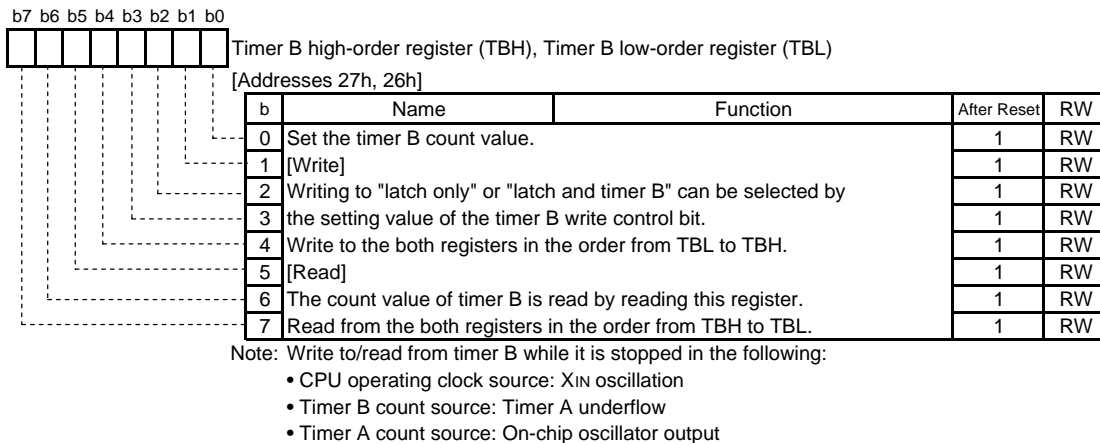


Fig.4.30 Configuration of Timer B high-order register, Timer B low-order register

Prescaler 1

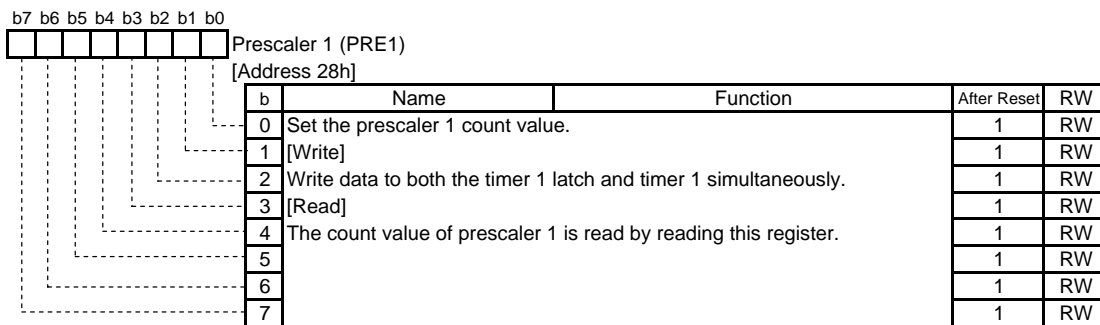


Fig.4.31 Configuration of Prescaler 1

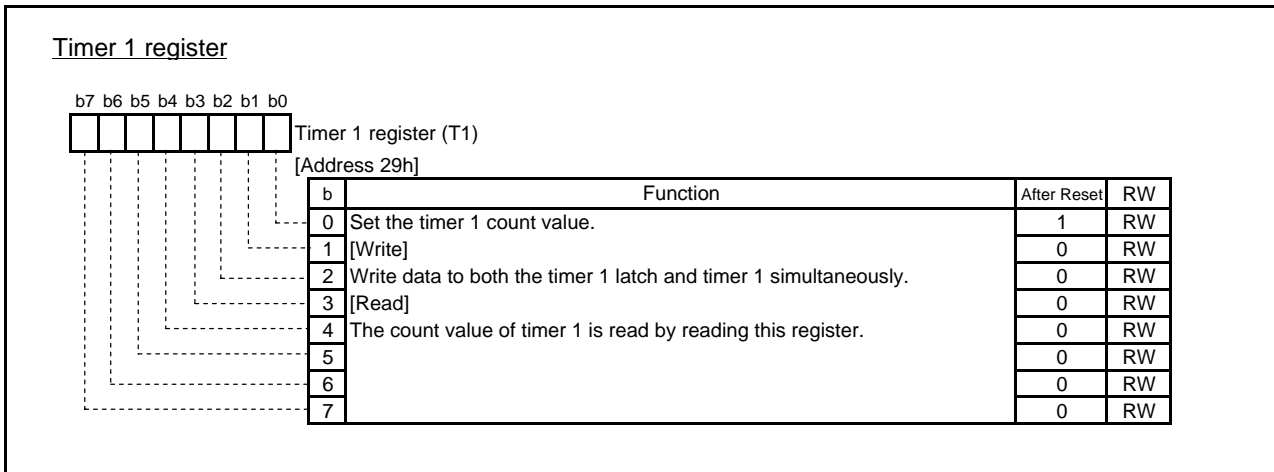


Fig.4.32 Configuration of Timer 1 register

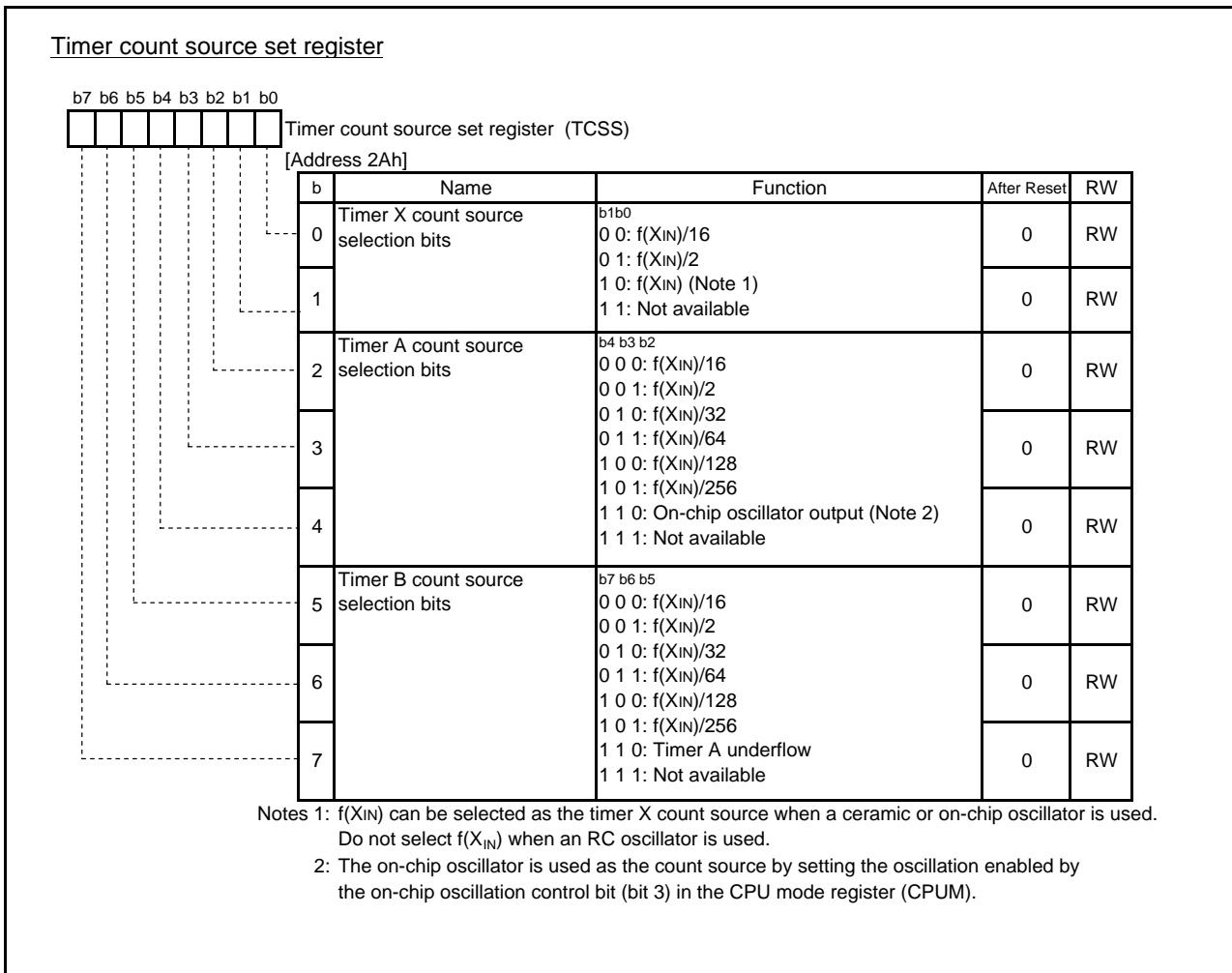


Fig.4.33 Configuration of Timer count source set register

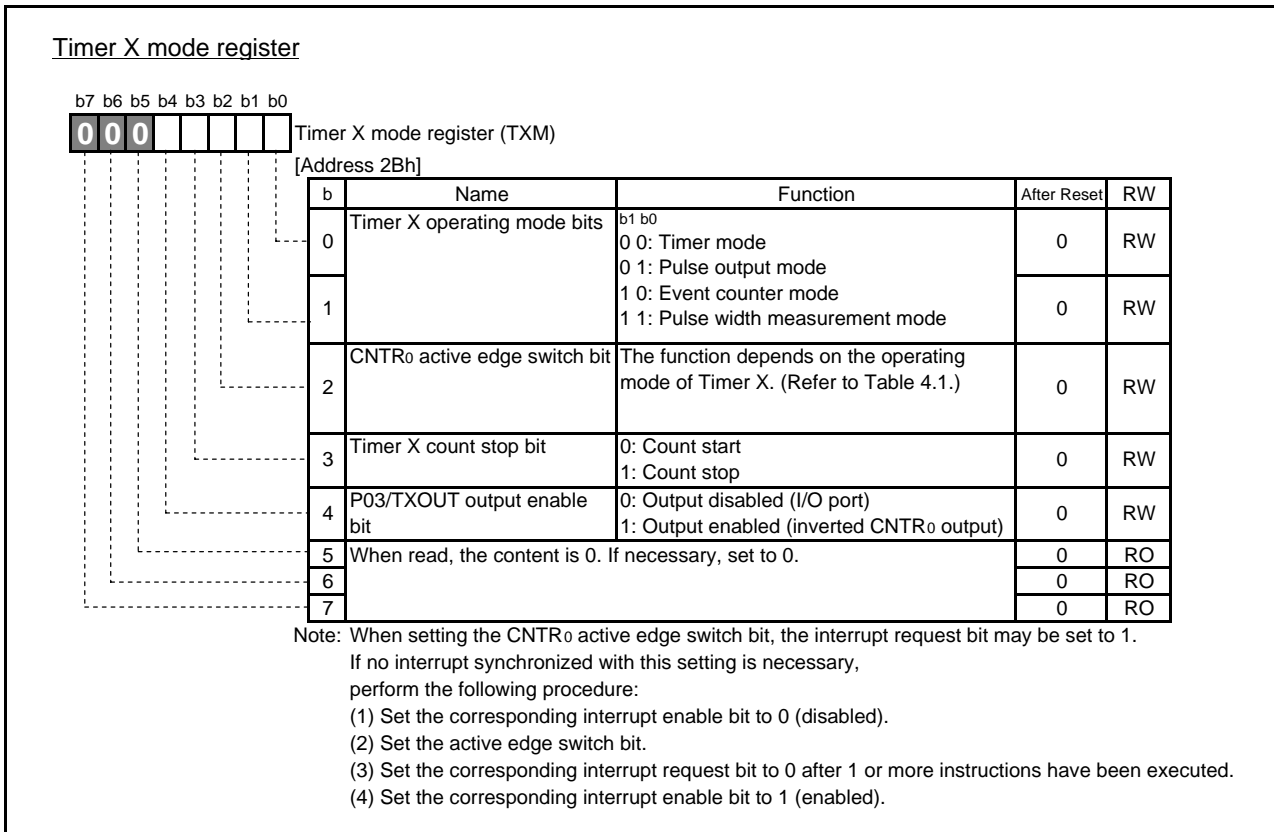


Fig.4.34 Configuration of Timer X mode register

Table 4.2 CNTR0 active edge switch bit function

Timer X operation mode	Set value	Timer function selection	CNTR0 interrupt request occurrence source
Timer mode	0	—	CNTR0 input signal falling edge (no influence to timer count)
	1	—	CNTR0 input signal rising edge (no influence to timer count)
Pulse output mode	0	Pulse output start from "H"	Output signal falling edge
	1	Pulse output start from "L"	Output signal rising edge
Event counter mode	0	Count at rising edge	Input signal falling edge
	1	Count at falling edge	Input signal rising edge
Pulse width measurement mode	0	Measure "H" pulse width	Input signal falling edge
	1	Measure "L" pulse width	Input signal rising edge

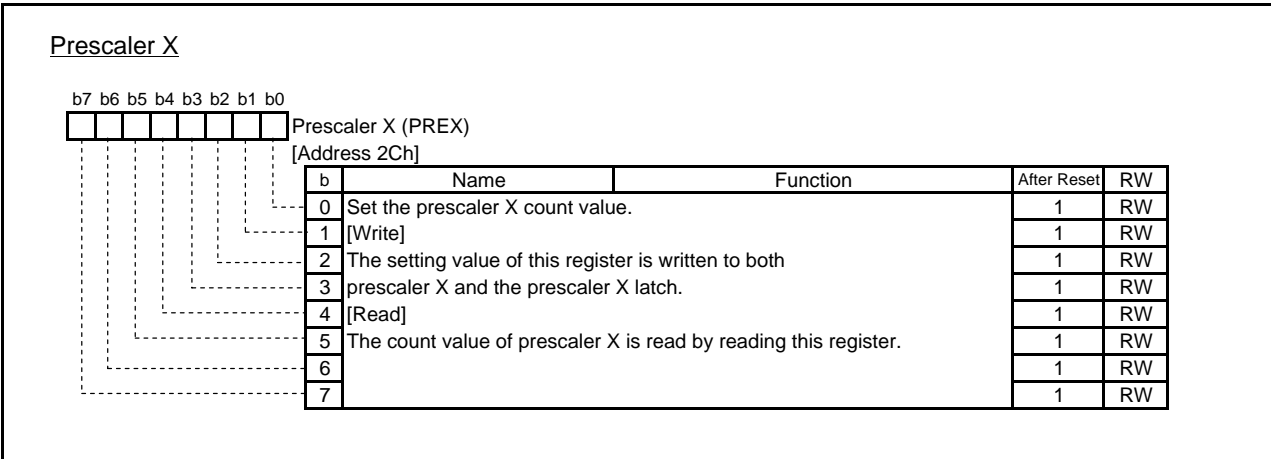


Fig.4.35 Configuration of Prescaler X

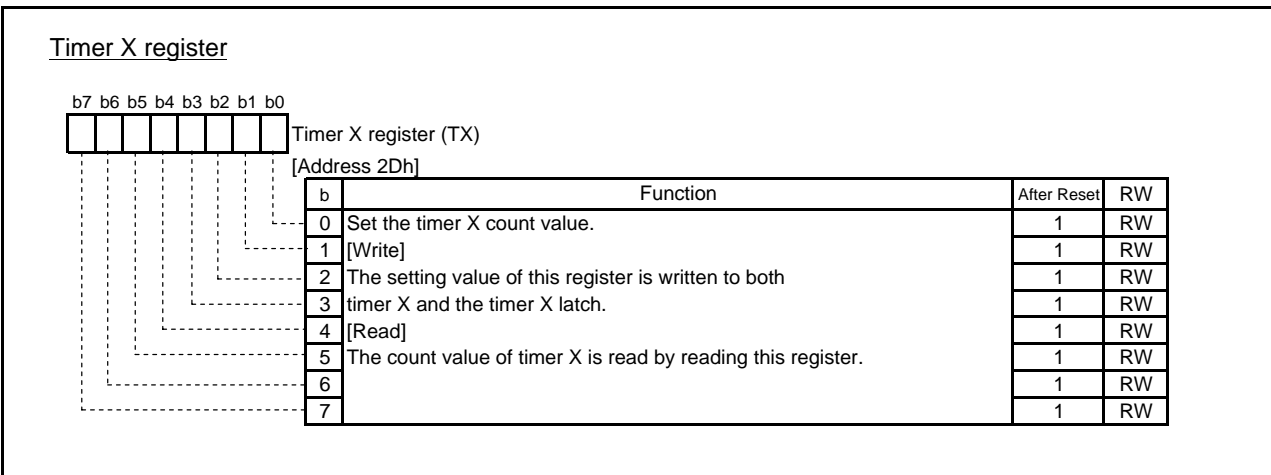
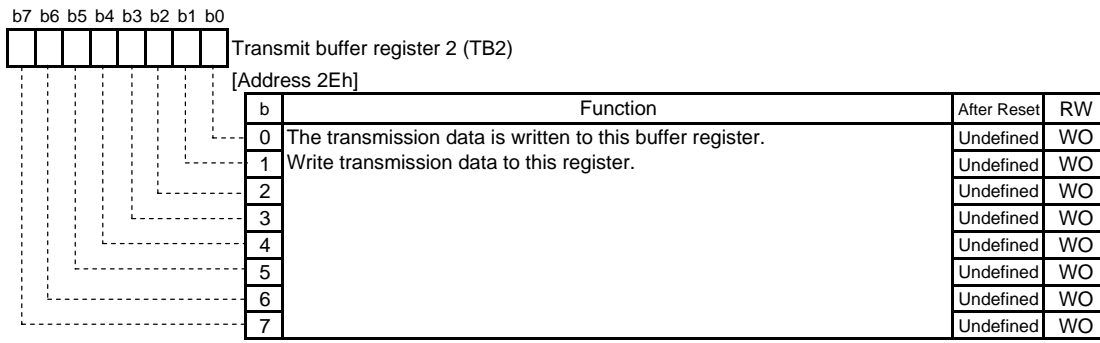


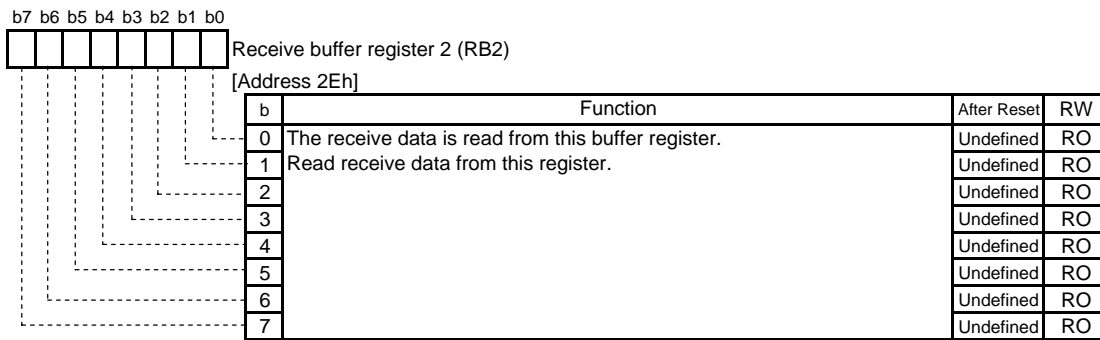
Fig.4.36 Configuration of Timer X register

Transmit buffer register 2



Note: This register is assigned to the same address as the receive buffer register. Unreadable.

Receive buffer register 2



Note: This register is assigned to the same address as the transmit buffer register. Unwritable.

Fig.4.37 Configuration of Transmit buffer register 2/Receive buffer register 2

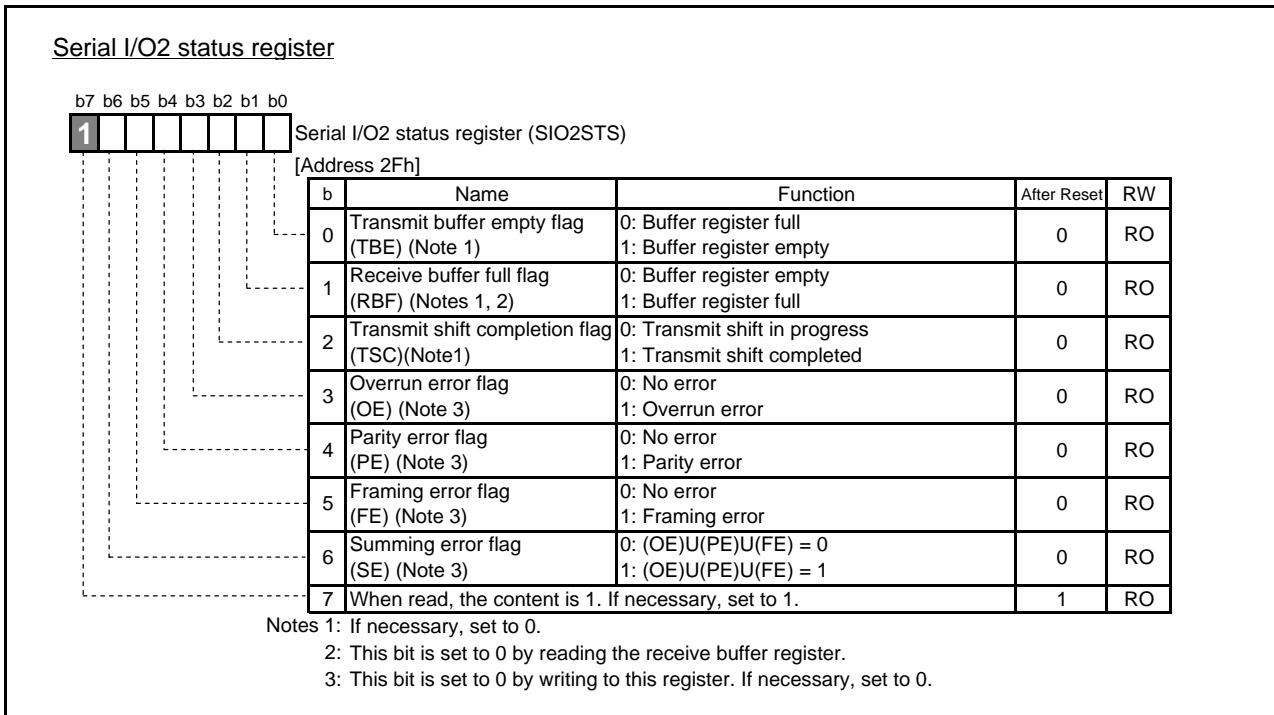


Fig.4.38 Configuration of Serial I/O2 status register

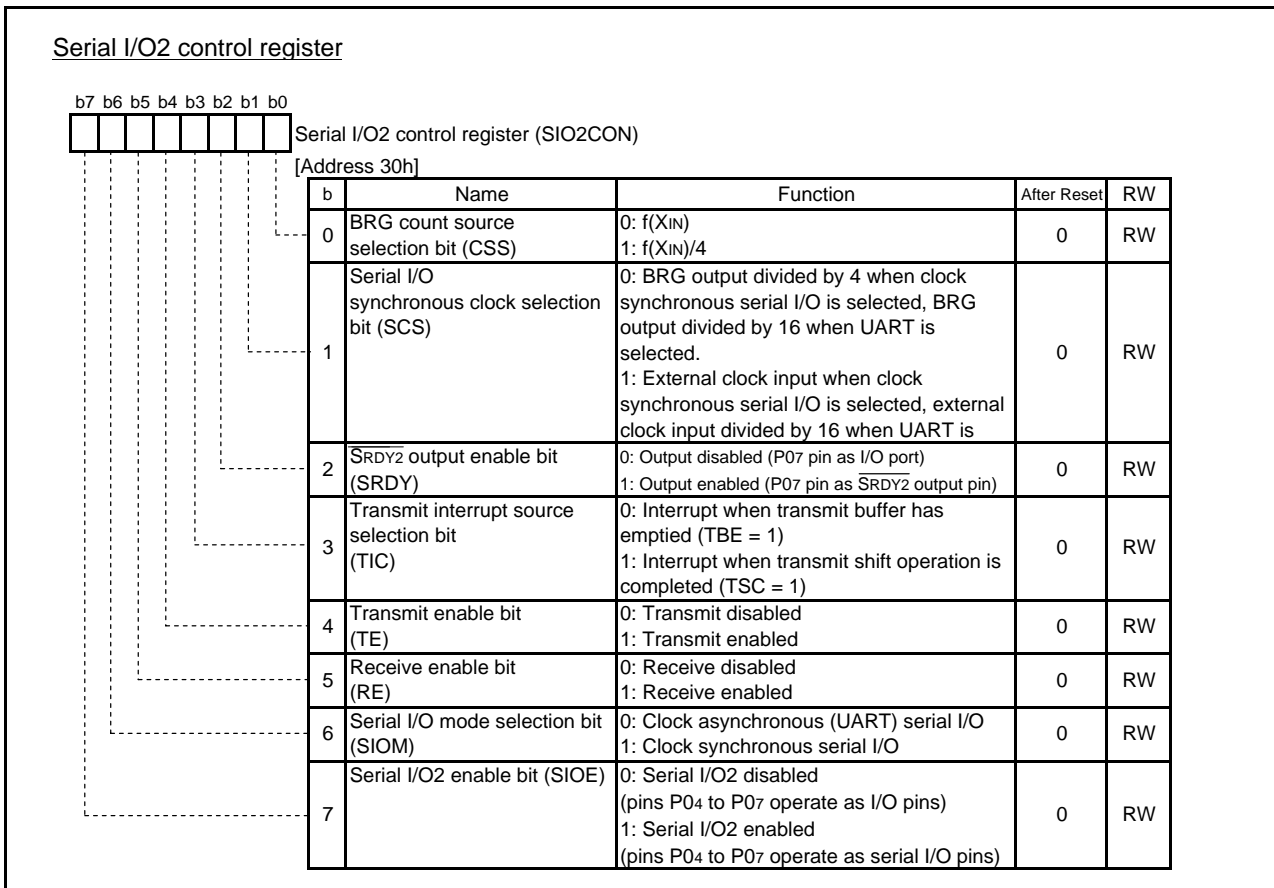


Fig.4.39 Configuration of Serial I/O2 control register

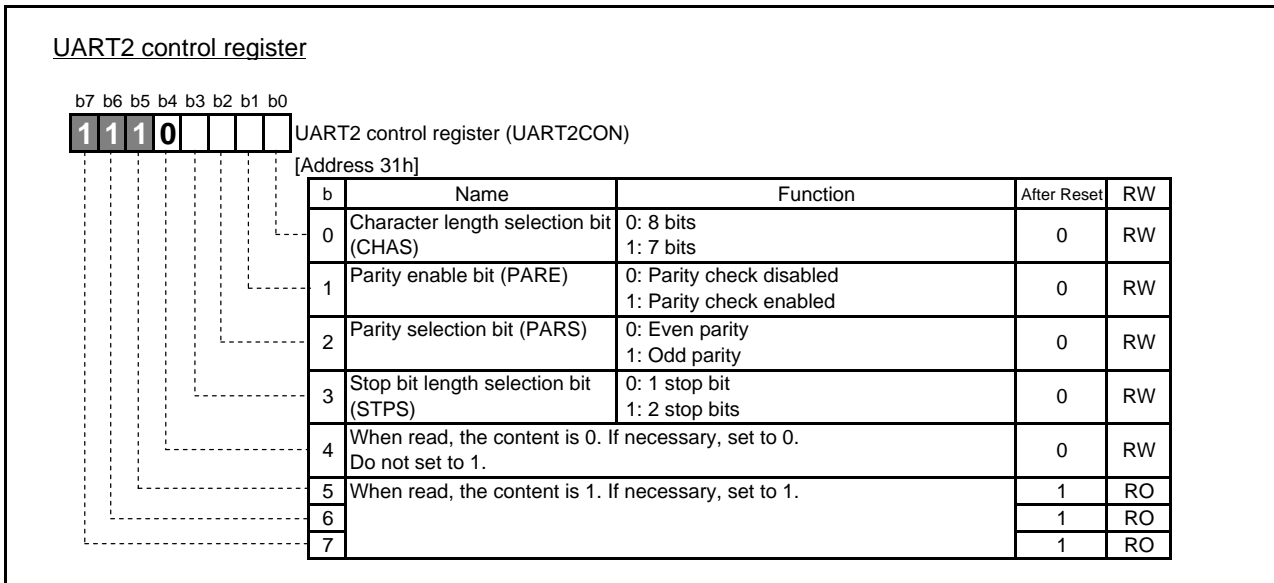


Fig.4.40 Configuration of UART2 control register

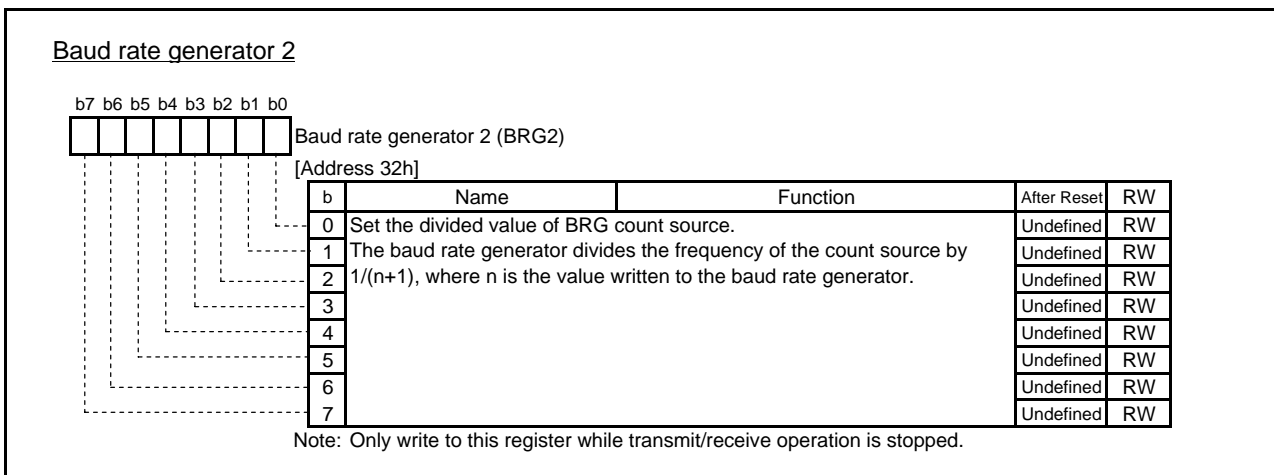


Fig.4.41 Configuration of Baud rate generator 2

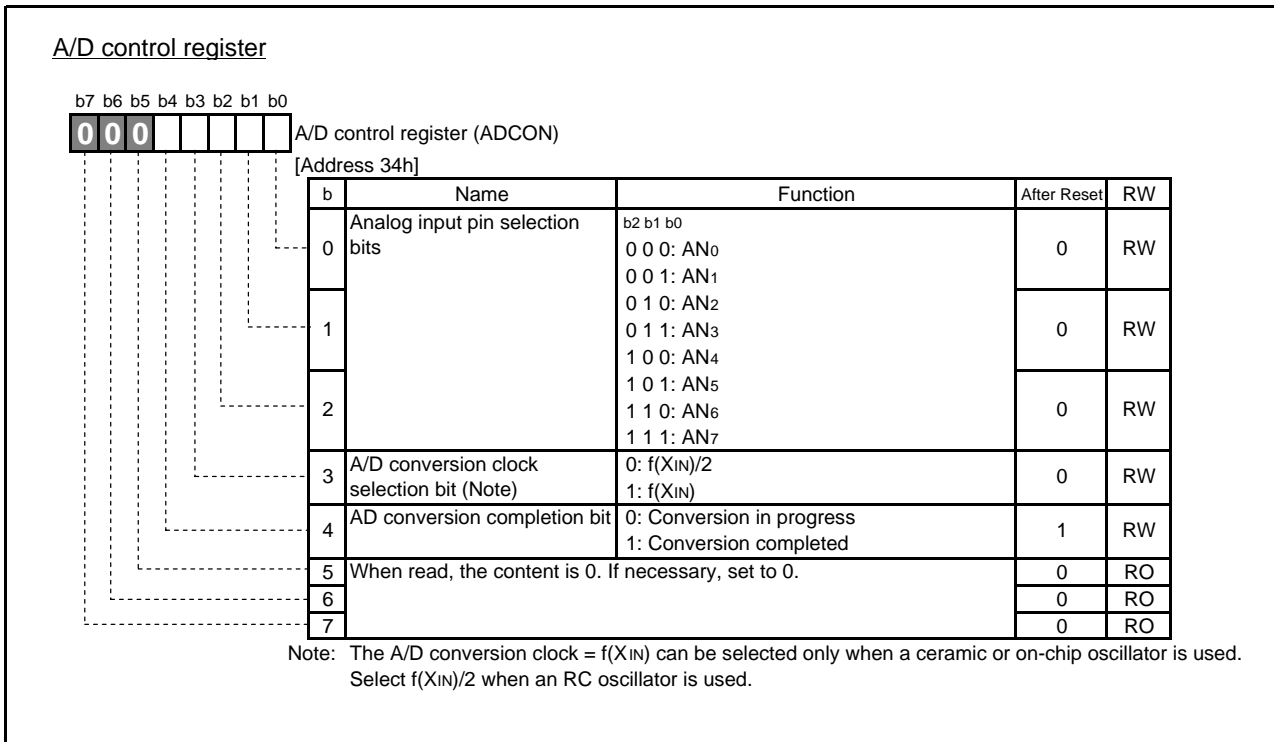


Fig.4.42 Configuration of A/D control register

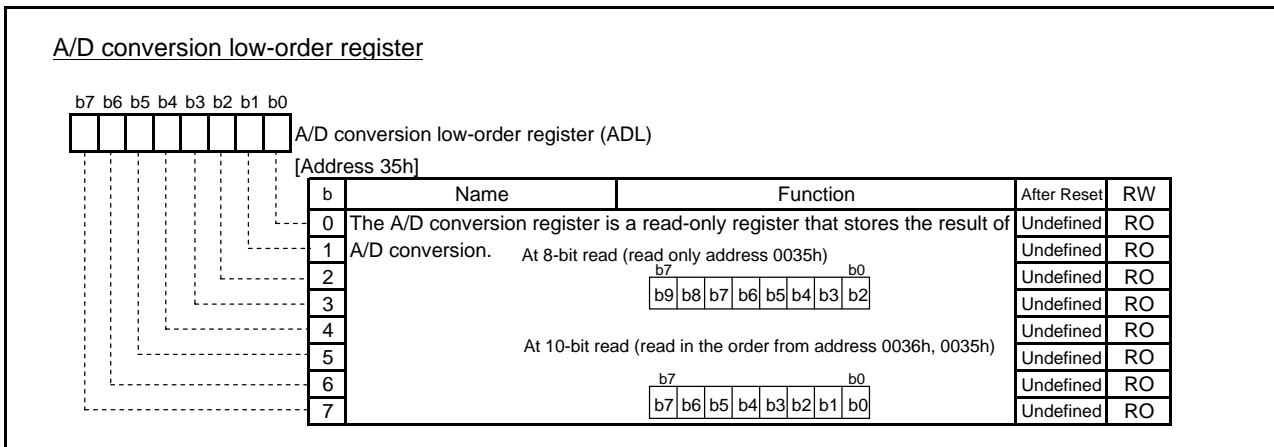


Fig.4.43 Configuration of A/D conversion low-order register

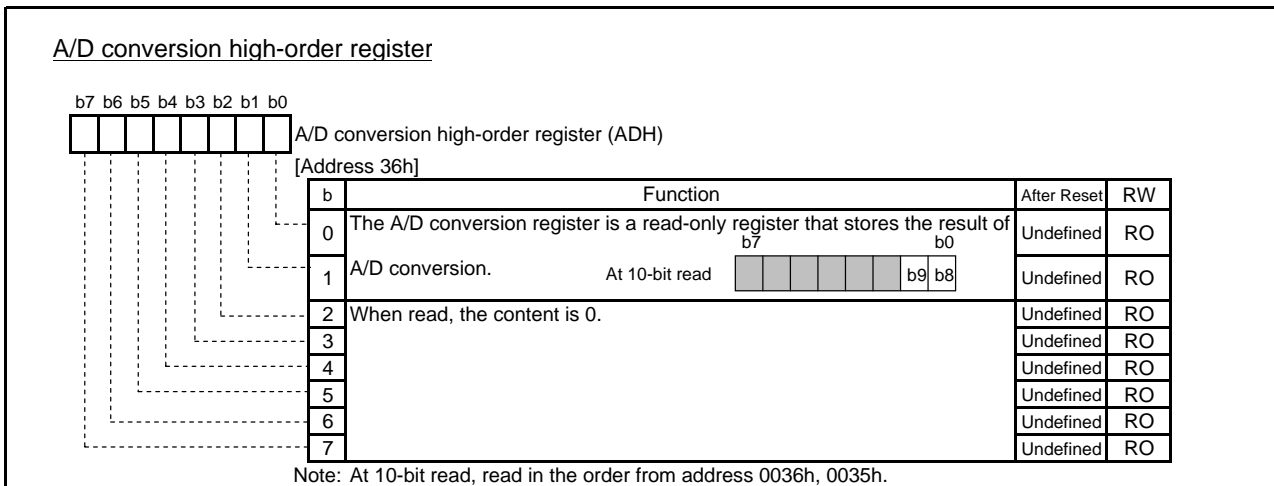


Fig.4.44 Configuration of A/D conversion high-order register

On-chip oscillation division ratio selection register

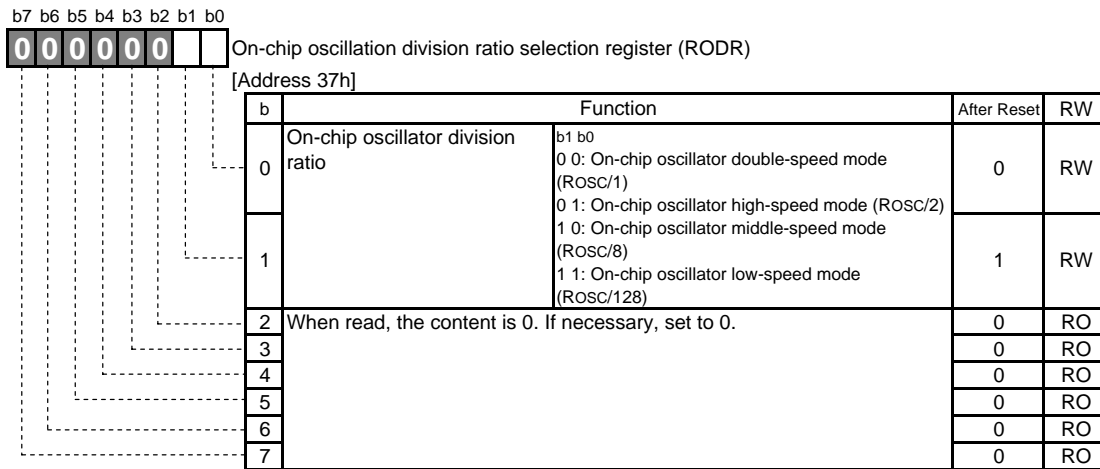
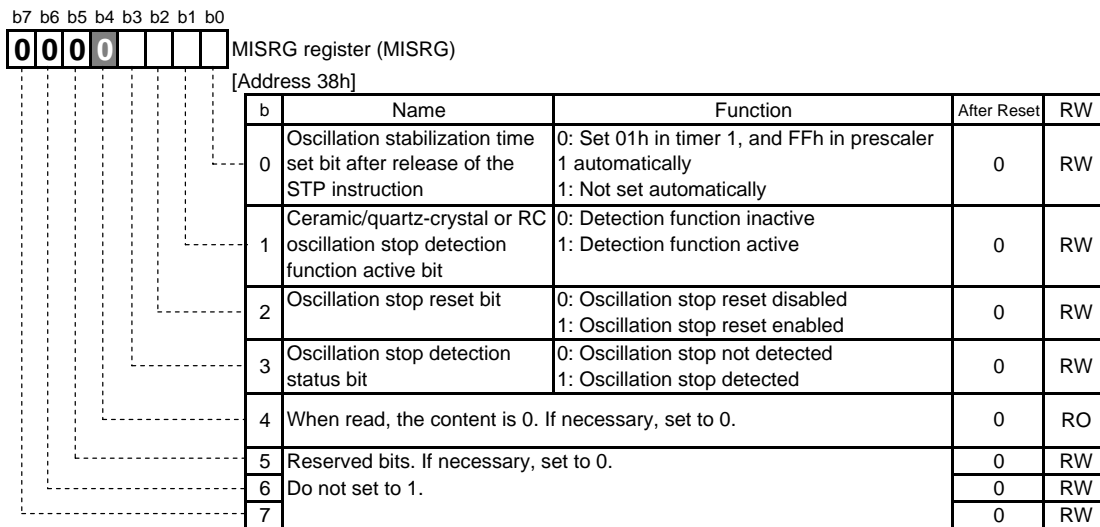


Fig.4.45 Configuration of On-chip oscillation division ratio selection register

MISRG



- Notes 1: The ceramic or RC oscillation stop detection function active bit is not initialized by the oscillation stop internal reset.
This allows the oscillation stop detection circuit to be in active when the MCU is returned from a reset occurred on oscillation stop detection.
- 2: The oscillation stop detection status bit is initialized in the following:
- External reset
 - Write 0 to the ceramic or RC oscillation stop detection function active bit
- 3: The oscillation stop detection circuit is not included in the emulator MCU "M37542RSS".

Fig.4.46 Configuration of MISRG

Watchdog timer control register

b7 b6 b5 b4 b3 b2 b1 b0



Watchdog timer control register (WDTCN)

[Address 39h]

b	Name	Function	After Reset	RW
0	Watchdog timer H		1	RO
1	(read only for high-order 6-bit)		1	RO
2			1	RO
3			1	RO
4			1	RO
5			1	RO
6	STP instruction function selection bit (Note 1)	0: Enter to stop mode at STP instruction execution 1: Internal reset at STP instruction execution	0	RW
7	Watchdog timer H count source selection bit (Note 2)	0: Watchdog timer L underflow 1: On-chip oscillator/16 or $f(X_{IN})/16$ (Note 3)	0	RW

Notes 1: This bit can be written to only once after releasing reset. After writing, a write to this bit is disabled because it is locked.

The function of this bit can also be set using bit 3 of the function set ROM data 2 (FSROM2). If used, this bit value is fixed to the same as the bit 3 value and cannot be changed by a program. Also, a value set by bit 3 changes the initial value of this bit after reset.

2: The function of this bit can also be set using bit 2 of FSROM2. If used, this bit value is fixed to the same as the bit 2 value and cannot be changed by a program. Also, a value set by bit 2 changes the initial value of this bit after reset.

3: When double-speed mode, high-speed mode, or middle-speed mode is selected by the clock division ratio selection bits (bits 7, 6 in CPU mode register), the count source clock of the watchdog timer H is set to $f(X_{IN})/16$.

When the supply from on-chip oscillator is selected, it is set to the on-chip oscillator output/16.

4: After reset, this register sets the watchdog timer to FFFFh and start counting. Counting can be automatically started by bit 1 of FSROM2 after reset.

Fig.4.47 Configuration of Watchdog timer control register

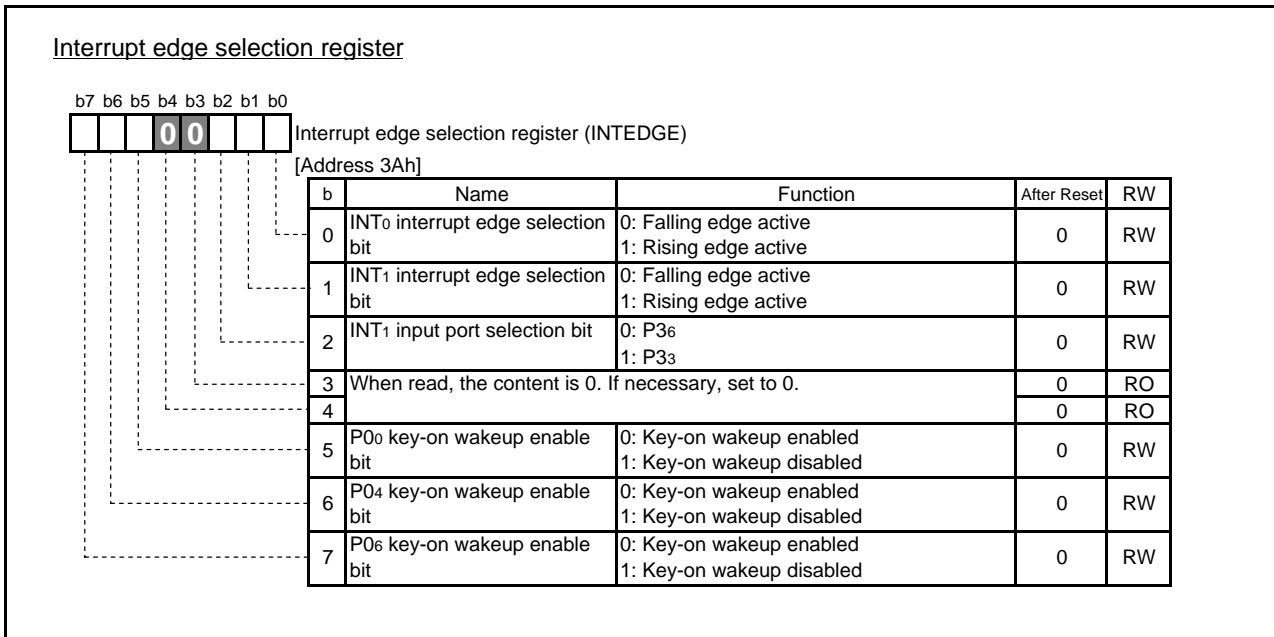


Fig.4.48 Configuration of Interrupt edge selection register

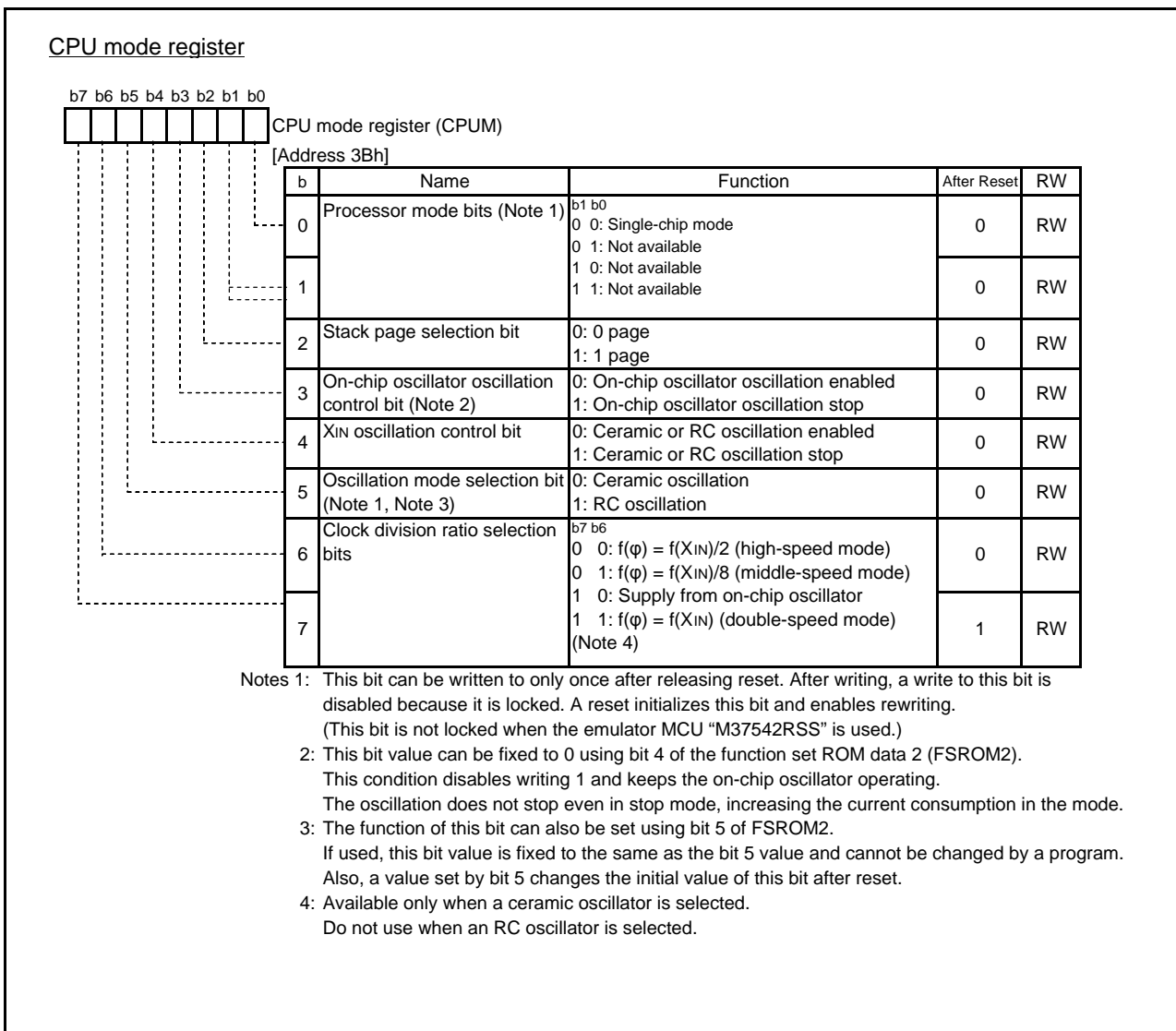


Fig.4.49 Configuration of CPU mode register

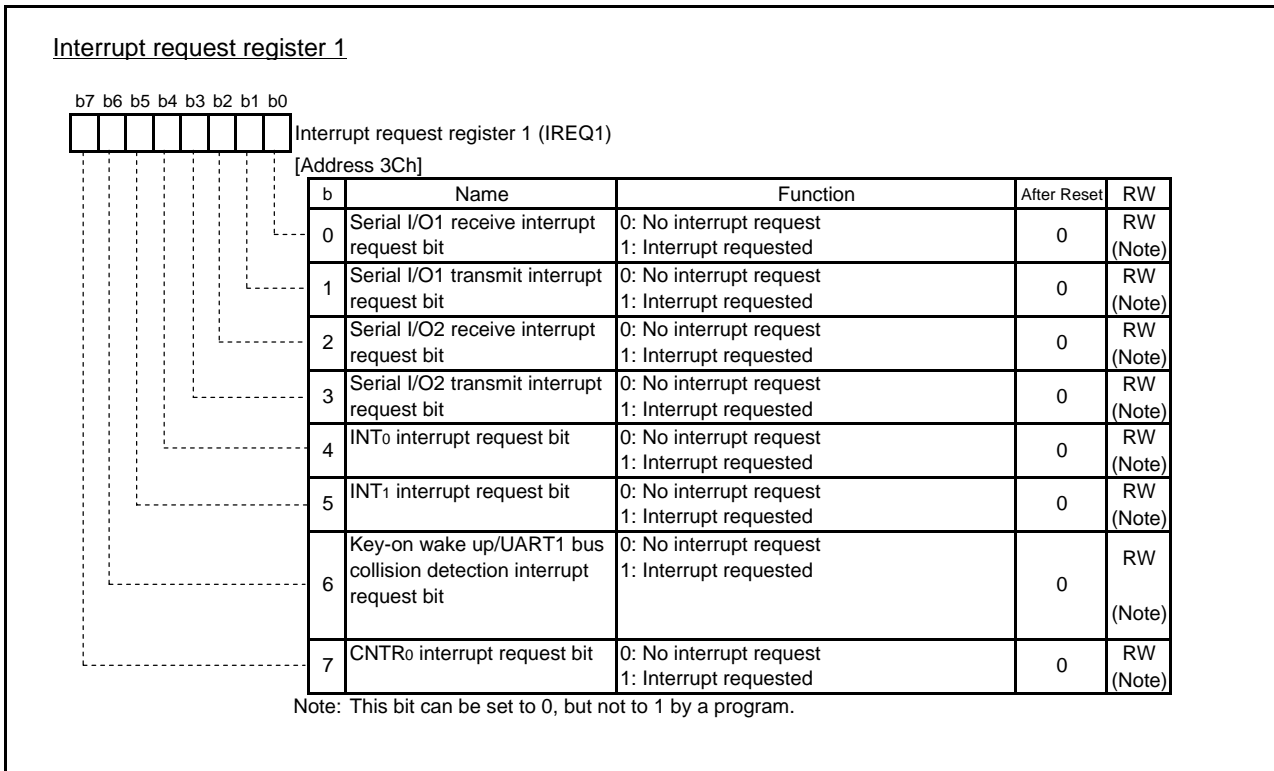


Fig.4.50 Configuration of Interrupt request register 1

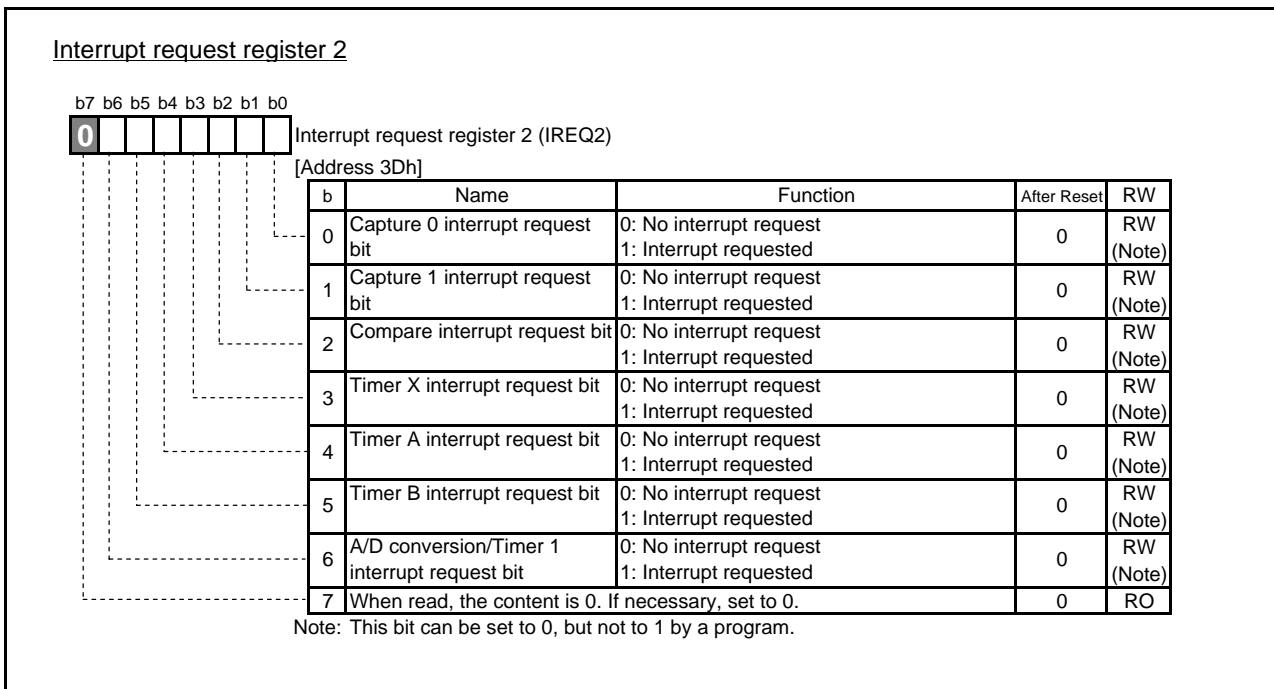


Fig.4.51 Configuration of Interrupt request register 2

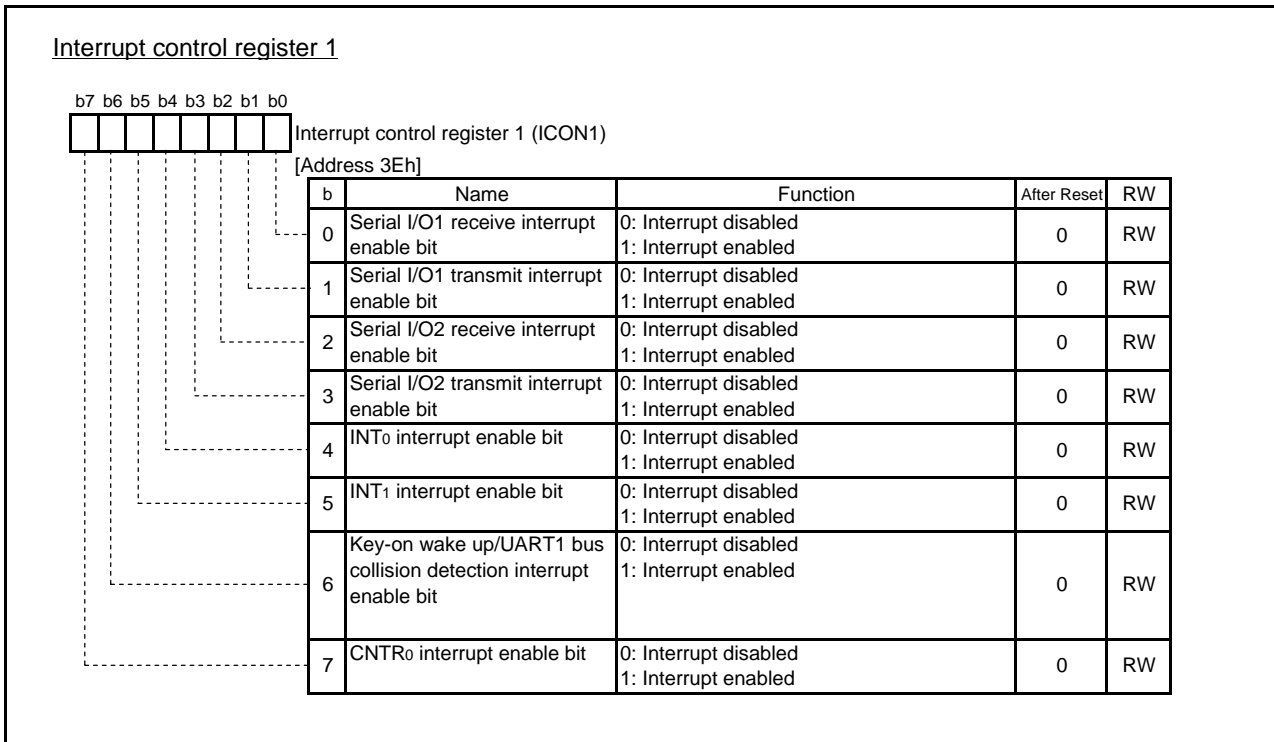


Fig.4.52 Configuration of Interrupt control register 1

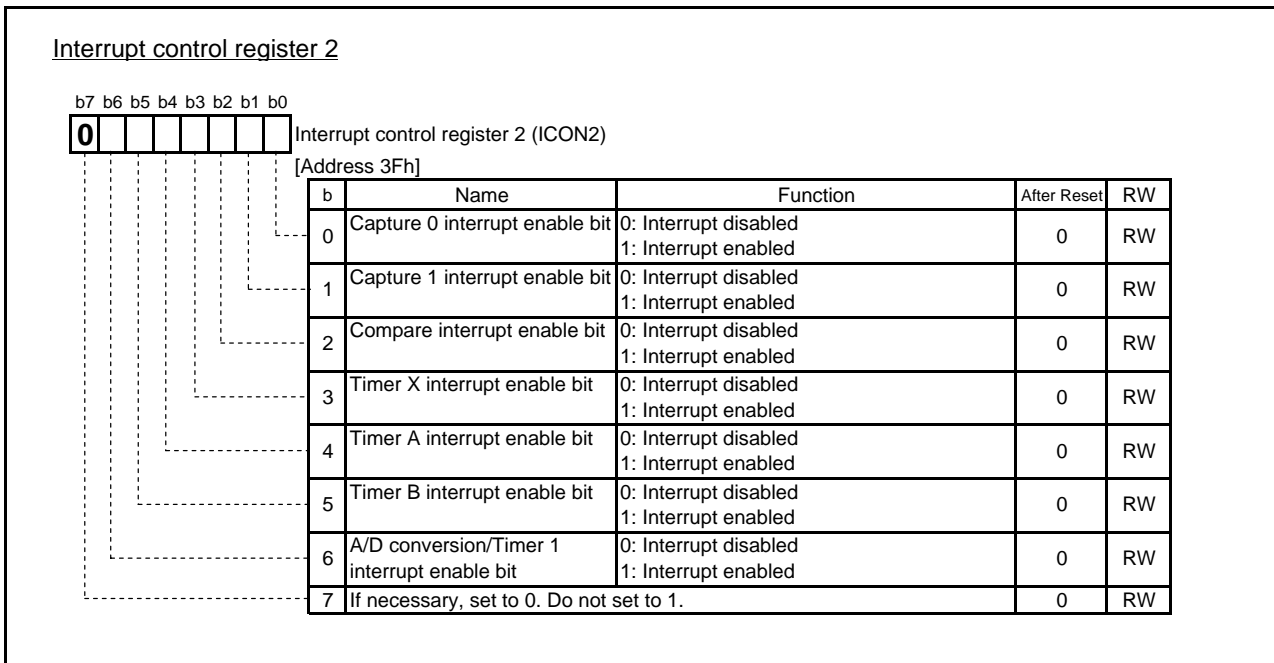


Fig.4.53 Configuration of Interrupt control register 2

The function set ROM data 0, 1 and 2 are used to set peripheral functions by writing data to QzROM and cannot be set by a program. Data written to these areas become valid after releasing reset. Regardless of the use of peripheral functions, always set a value according to the system.

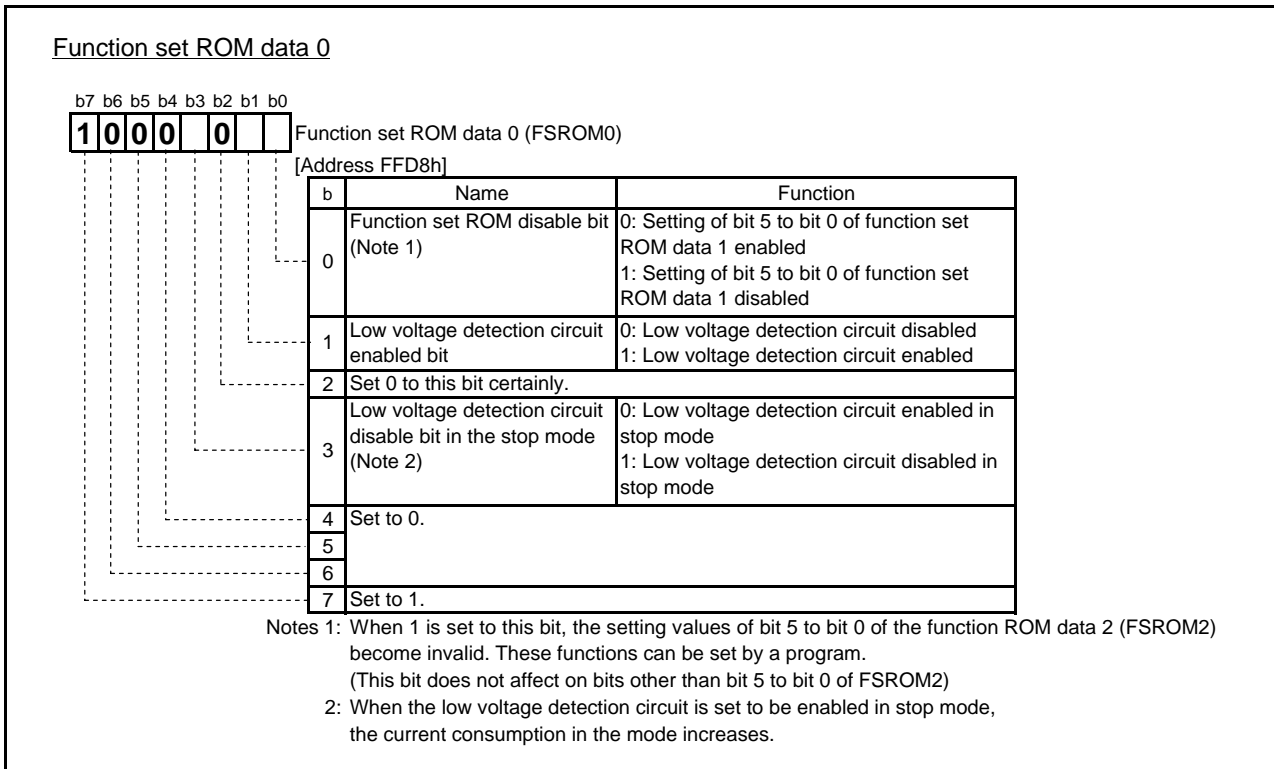


Fig.4.54 Configuration of Function set ROM data 0

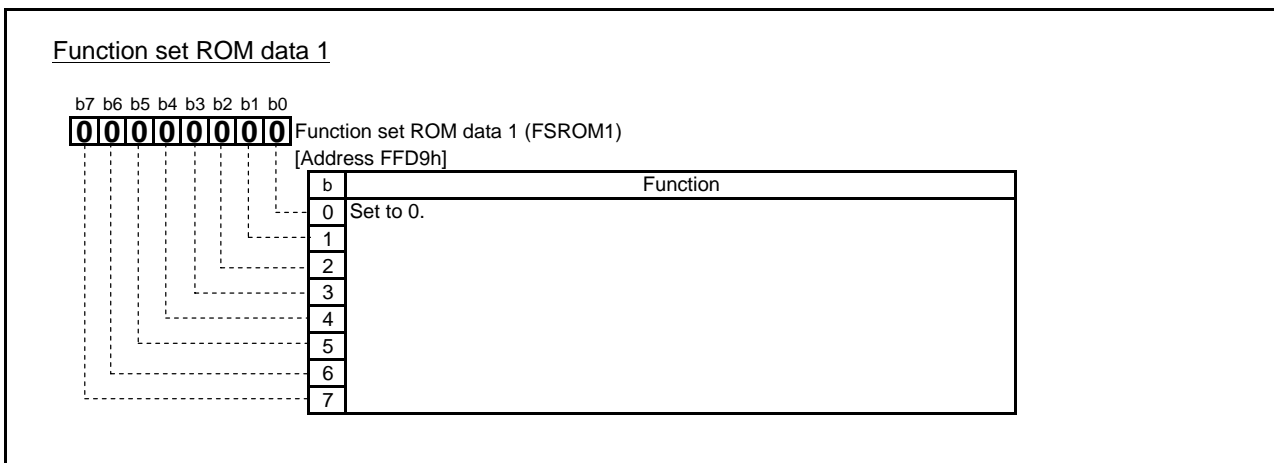
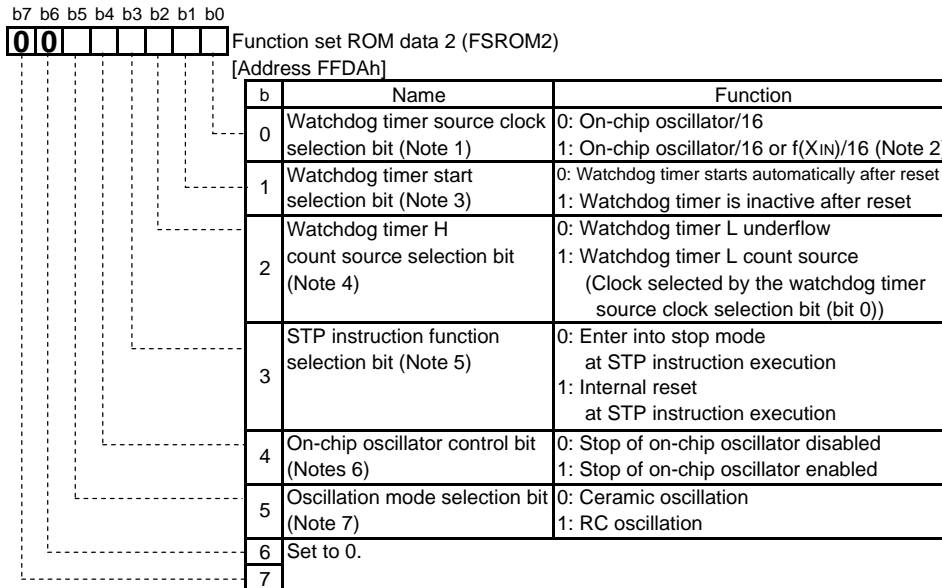


Fig.4.55 Configuration of Function set ROM data 1

Function set ROM data 2



- Notes 1: This bit is enabled when the function set ROM disable bit (bit 0 of FSROM0) is set to 0. When the function set ROM disable bit is set to 1 (disabled), the watchdog timer source clock is set to f(X_{IN})/16.
- 2: When double-speed mode, high-speed mode, or middle-speed mode is selected by the clock division ratio selection bits (bits 7, 6 of CPUM), the watchdog timer source clock is set to f(X_{IN})/16. When the supply from the on-chip oscillator is selected, it is set to the on-chip oscillator output/16.
- 3: This bit is enabled when the function set ROM disable bit is set to 0. When the function set ROM disable bit is set to 1 (disabled), the watchdog timer is stopped after reset. The watchdog timer starts counting by writing to the watchdog timer control register.
- 4: This bit is enabled when the function set ROM disable bit is set to 0. When the function set ROM disable bit is set to 1 (disabled), the watchdog timer H count source is selected by bit 7 of the watchdog timer control register (address 0039h).
- 5: This bit is enabled when the function set ROM disable bit is set to 0. When the function set ROM disable bit is set to 1 (disabled), the STP instruction function is selected by bit 6 of the watchdog timer control register (address 0039h).
- 6: This bit is enabled when the function set ROM disable bit is set to 0. Setting 0 to this bit fixes bit 3 of the CPU mode register to 0 (on-chip oscillator oscillation enabled) and the on-chip oscillator cannot be stopped. The oscillation does not stop even in stop mode, increasing the current consumption in the mode. When the function set ROM disable bit is set to 1 (disabled), the on-chip oscillator operation is selected by bit 3 of the CPU mode register (address 003Bh).
- 7: This bit is enabled when the function set ROM disable bit is set to 0. When the function set ROM disable bit is set to 1 (disabled), the oscillation method is selected by bit 5 of the CPU mode register (address 003Bh).

Fig.4.56 Configuration of Function set ROM data 2

5. Reference Documents

Datasheet

7547 Group Datasheet

The latest version can be downloaded from the Renesas Technology website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Technology website.

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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Feb 20, 2007	—	First edition issued

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